

1 Theory

1.1 Dislocation photoluminescence

Several investigations have documented that dislocations in silicon give rise to characteristic photoluminescence (PL) spectra below the band edge. First showed in [1] which labeled them D1 (0.812eV), D2 (0.875eV), D3 (0.934eV) and D4 (1.000eV). The samples were deformed at 850° C by bending, so that dislocation densities were inhomogeneous along the samples. [1] states that the intensity of these lines increase closer to the dislocation-rich parts of the crystal. At the same time the intensity of the intrinsic characteristics decrease. The distance between D1-D4 (62 ± 3 meV) corresponds to the energy of the optical phonons in silicon [1]. [1] reports that D1 and D2 are dominant in heavily deformed Si crystals, while D3 and D4 predominate in weakly deformed Si. A similar result was also reported by recent study [2] for small angle grain boundaries using cathodoluminescence.

It has been suggested in [3] that D1-D4 are due to dislocations which have been frozen in under low-shear stress. [3] state that photoluminescence under uniaxial stress shows that D1/D2 originate in the tetragonal defect with random orientation relative to $\langle 100 \rangle$ directions. [3] conclude that D3 and D4 are closely related, whereas the independent D1/D2 centers might be deformation-produced point defects in the strain region of dislocations. D1 and D2 is known to be closely related, as well as D3 and D4, and there have been no reports on the D-line spectrum missing only the D1 line [4].

The origin of D1 and D2 is not clear. It has been argued that they originate in electronic transition at the geometrical kinks on dislocations [5], point defects [3] and impurities [6] and/or from the reaction products of dislocations [7]. On the other hand, D3 and D4 lines are generally thought to be related to electronic transition within dislocation cores [8]. In addition, it has been suggested that the D3 line most likely is a phonon-assisted replica of D4 [8].

New lines D5 and D6 emerge when high-temperature, low-stress deformation is followed by low-temperature, high-stress deformation. [3] propose that line D5 is due to straight dislocations and D6 is due to stacking faults. [3] also suggest that D3/D4 photoluminescence is much more characteristic of the dislocations themselves than the D1/D2 emission lines. [9] state that D5 is correlated with electron-hole recombination at localized centers on separate partial dislocations. After annealing at moderate temperatures ($T > 360^\circ\text{C}$) the new lines merge into D4 [9].

Both [1] and [3] studied plastically deformed silicon made by the Czochralski process (Cz-Si). [10] studied dislocations in multicrystalline silicon (mc-

Si) and found similar lines with the entire set of D-lines shifted with around 10meV, presumably due to a strain field. Using a laser annealing technique [11], introducing dislocations on a Cz-Si wafer, confirm the band location of D1-D4 from [3] in [10]. A principal difference between dislocation D'-lines in mc-Si versus D-lines in Cz-Si is a substantial broadening (60-70meV at 77K) of the D1'/D2' lines [10].

Cz-Si [1]	D1 0.812eV	D2 0.875eV	D3 0.934eV	D4 1.000eV
mc-Si [10]	D1' 0.80eV	D2' 0.89eV	D3' 0.95eV	D4' 1.00eV

Table 1: Energy positions of dislocation D-lines in Cz-Si and D' bands in mc-Si

[10] reveal a linear dependence of the band-to-band photoluminescence intensity and minority carrier lifetime across entire multicrystalline-Si wafers. Photoluminescence mapping in [10] of the 0.78eV (0.8eV) band intensity reveal a linkage to areas of a high dislocation density. This band should also be visible in room temperature [10].

Dislocation related lines (D-lines) has been observed in low temperature photoluminescence spectra from the regions which included the intragrain defects. [4] concluded that grain boundaries are not active recombination centers. [4] also show a TO-phonon replica of the boron bound exciton at 1.093eV. Intensity of boron bound exciton from the long lifetime regions was higher than that from the short lifetime regions. D-lines reported by [3] are in a short lifetime region. For a long lifetime region, [4] observe a peak at 1.00eV which is not the D4 line, but the zone center optical phonon sideband of the two-hole transition in the boron bound exciton [12].

It is believed that the intra-grain defects observed in the photoluminescence mapping are dislocations decorated with the heavy metals [4]. [13] found that if the contamination level is too low, or too high (dislocation decorated by metal silicate precipitates) the defect photoluminescence band vanished in room temperature. However, a relatively low contamination level of dislocations, in the order of 10 impurity atoms per micron of the dislocation length produces distinguishable defect band luminescence [13].

[14] conclude that defects are metal contaminated dislocation clusters which originated from small angle grain boundaries. [14] study origins of the defects by low temperature photoluminescence spectroscopy, electron backscatter diffraction pattern measurement and the etch-pit observation. [15] demonstrate three areas of a sample with only D3 and D4 present, and

conclude that this is due low concentration of metallic impurities.

1.2 Impurities

Diffusion of transition metals into silicon crystals result in a variety of different electrically active levels in the forbidden bandgap. Impurities is also known to create precipitates inside a silicon crystal, which change the photoluminescence spectra compared to interstitial impurities.

There are several units of impurities in silicon that's commonly used. Examples are: ppbw (Parts Per Billion by Weight), ppba (Parts per Billion Atomic) and atoms/ cm^3 . To convert from ppbw to atoms/ cm^3 , the following equation can be used:

$$atoms/cm^{-3} = \frac{10^{-9} [ppbw] \cdot N_A \cdot [density(Si)]}{[atomicmassofelement]} \quad (1)$$

where N_A is Avogadro's number, density(Si) is in g/ cm^3 , and atomic mass is in g/mole. To convert from ppba to ppbw:

$$ppbw = \frac{[atomicmassofelement]}{[atomicmassofSi]} \quad (2)$$

1.2.1 Atom impurities

Early work done by [12] compare intrinsic silicon from the Czochralski process with doped silicon. [12] do extensive photoluminescence study with doping atoms As, P, Sb, Bi, B, Ga, In and Al. The high intensity transverse optical lines occur at 1.0907eV, 1.0916eV, 1.0921eV, 1.0888eV, 1.0924eV, 1.0914eV, 1.0835eV and 1.092eV respectively with the different doping atoms present. Impurities like carbon complexes with many impurities in silicon, resulting in a large variety of photoluminescence centers. Detected complexes are another C atom, one oxygen atom, one N atom, one Ga atom, the four-lithium atom complex, beryllium and numerous radiation damage centers, especially involving oxygen [16]. See appendix 5 for energies.

Doping atoms give rise to different characteristics in the photoluminescence spectra as well. Boron doping exhibits a line right below the silicon bandgap. That particular peak is hard to detect due to a strong luminescence from the silicon itself, but its phonon replicas can be identified (figure 27). Phosphorous doping give rise to a line just below the boron line (figure 28).

Some impurities does not result in any specific photoluminescence spectra, like interstitial chromium [17]. Atleast not for wavelengths up to 1800nm.

However, chromium bound with a boron atom can be identified as a peak around 0.85eV where the intensity increase linearly with laser power [17, 18]. Photoluminescence from another impurity, titanium, has been observed around 2.85eV in 4H silicon carbide by [19], and in 6H by [20] at 2.79eV, 2.82eV and 2.86eV named ABC lines (figure 32). These energies are far beyond that of the silicon bandgap, and can in cases described above, be uniquely identified.

Many of the other identified impurities are located just below the silicon bandgap in the photoluminescence spectra. Spectra for a silicon sample with a low amount of impurities can be seen in figure 26. Copper doping of silicon crystals results in an intense emission at 1.014eV [21]. [9] study Cu doped Si and also observe a shoulder on the D1 line which presumably arises from Cu precipitates at the dislocation.

Another important impurity is iron. [22] observe a spectrum of 0.735eV, which relate to a complex defect containing iron. Here the sample was introduced with Fe atoms into a float-zone silicon crystal (PL at figure 29). An earlier study [23], observe a luminescence spectra around 1.07eV in boron-doped, iron-diffused crystalline silicon and suggest the source is Fe-B pairs. Interstitial iron Fe, is about 10 times more effective as a recombination center than Fe-B pairs by low-level lifetime measurements and therefore reduces the minority carrier diffusion length more strongly (PL at figure 30) [24].

Recent work in [25] show that micro-photoluminescence is an excellent tool for identifying metal precipitates in silicon as seen in figure 1. Iron images in [26] reveal internal gettering of iron to grain boundaries and dislocated regions during ingot growth. The minimum size for detection is $1\mu\text{m}$, or even smaller, since the photoluminescence signal might be broadened. Precipitates from Fe and Cu are detected due to reduced band to band recombination intensity. Iron in silicon also affect the defect photoluminescence [25].

1.2.2 Interaction with dislocations

Investigation in [27] show that transition-metal contamination plays an important role in the production of D-band luminescence from silicon samples containing either epitaxial stacking faults or oxidation-induced stacking faults. [11] found that Cu doping resulted in reduced intensity of D1 and D2, and the intensity of D3 and D4 become very small. [9] demonstrate that a complete passivation of the D-band luminescence is achieved at higher Cu and Fe concentration when deliberately contaminating high purity silicon samples which contain dislocations. However impurities like Ni, lead to no detectable changes in the spectrum [9]. D-band recombination in Si is found

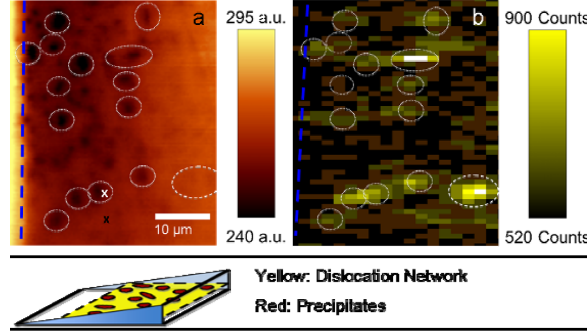


Figure 1: Bottom: Scheme of the sample preparation with the polished angle. Top: A Intensity of the BB PL peak at room temperature (a), and of the iron X-ray K α fluorescence (b) from [25]. The dislocation network intersects the surface to the right of the dashed blue line. The white circles show recombination active precipitates.

to be independent of impurities trapped at dislocations [9], and [7] concluded that metallic impurities don't seem to be related to D1 and D2 luminescence. Even so, it is still generally accepted that metal impurity influence it. Metal precipitation at crystal defects during the crystal growth can clean grains from impurities, and thus improve the performance as suggested for iron in [28]. A recent example of interaction with defects is iron precipitates in [25], showing an enhanced defect photoluminescence at $1.3\mu\text{m}$ (0.95eV). The same study show that copper contamination almost completely suppress the defect photoluminescence. This is in agreement with [11]. Suppression of defect photoluminescence by high copper concentrations was also reported in [29]. Cu precipitates can be located by reduced intensity of the band to band photoluminescence peak, both in areas with dislocations, and without [25].

Electron hole droplets (EHD), free excitons (FE) and bound excitons (BE) localized on phosphorus atoms has been steadily observed in [30] with photoluminescence on samples with low-dislocated regions. When increasing dislocation density the FE, BE and EHD bands decrease sharply. This may be due exciton capture by dislocation lines D1,D2 and non-radiative recombination [30]. EHD photoluminescence intensity is highly dependent on the pumping power [31]. There is a linear dependence, and pumping with 3mW or less makes it hardly visible in [31].

D1 line is shifted towards higher energies under uniaxial elastic deformation of samples with introduced dislocations or after their annealing in oxygen at 750°C [32]. Room temperature mapping of the 0.77eV band is attributed to oxygen precipitates in in thermally treated silicon made by the

Czochralski process (Cz-Si) [33]. The increase of this band on the dislocation lines is due to the preferential precipitation of oxygen [33]. Later, [34] state that the deep-level emission from multicrystalline silicon with an intensity maximum at 0.78eV at room temperature is different from that of the D1 line at low temperature. Furthermore, [34] suggest that the 0.78eV emission is associated with oxygen precipitation, and that the intra-grain defects are dislocation clusters decorated with oxygen impurities in addition to heavy-metal impurities. [35] state that the origin of trap densities in multicrystalline silicon could be structural crystal defects, which are highly decorated with oxygen precipitates.

2 Experimental

2.1 Samples

Name	Description	Feedstock
R6-Q3-210	Polysilicon, electronic grade, clean feedstock	Siemens process
ES1-Q3-201	Large amount of P and B, solar grade, dirty feedstock	From Elkem [36]
MH2-Q3-201	Same as ES1 with added Cr, solar grade, dirty feedstock	From Elkem [36]

Table 2: Samples

2.1.1 R6-Q3-201

This sample is from a clean feedstock, with low amount of impurities. B, Al and Fe were measured by Glow-Discharge Mass Spectrometry (GDMS), O and C were measured by Fourier transform infrared spectroscopy (FTIR).

Impurity	ppbw	atoms/cm ³
B	112.01	$1.45 \cdot 10^{16}$
Al	19.48	$1.0 \cdot 10^{15}$
Fe	nd	nd
C	2576	$2.26 \cdot 10^{17}$
O	1932	$8.87 \cdot 10^{16}$

Table 3: Impurities in R6

The impurities that are not listed were not analyzed, and are expected to be present in very low levels (tenths of ppbw).

2.1.2 ES1-Q3-201

This is a regular solar grade sample which originates from a compensated feedstock from Elkem Solar, from 90% ingot height. It has been Sopor etched to bring out dislocations [37].

Boron contaminants appear to be between 550 and 700 ppbw, which is between $7.1 \cdot 10^{16}$ and $9.7 \cdot 10^{16}$ atoms/cm³ respectively using 1. Phosphorus is measured around 1200-1500 ppbw, which is 5.4 - $6.8 \cdot 10^{16}$ atoms/cm³. Aluminum contaminants are just below $2.6 \cdot 10^{15}$ atoms/cm³. Other contaminants like Ti and Fe have very low values: less than $1.2 \cdot 10^{14}$ and

$3.8 \cdot 10^{14}$ atoms/cm³ respectively. For the lighter atom impurities, O have $1.7 \cdot 10^{17}$ atoms/cm³ and C have $6 \cdot 10^{17}$ atoms/cm³ [36].

2.1.3 MH2-Q3-201

This sample is almost identical to ES1, but the sample also have extra chromium added. Chromium contaminants appear to be between 2 and 5 ppbw [36] which corresponds to $5.4 \cdot 10^{13}$ and $1.3 \cdot 10^{14}$ atoms/cm³ respectively using 1, but exact concentration might be a little lower due detection limit of the instrument.

2.2 Setup

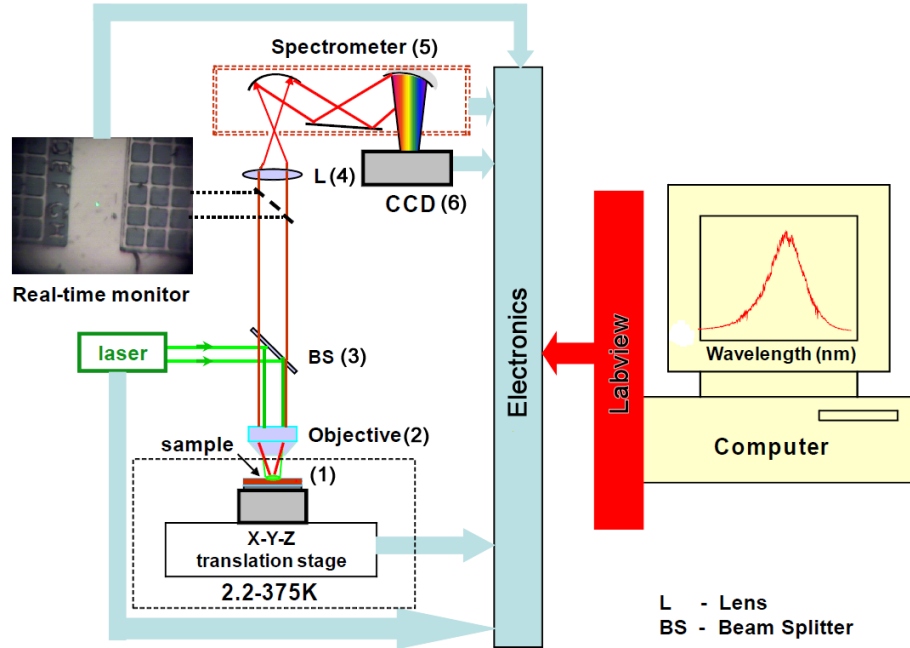


Figure 2: Lab setup

#	Part	Product #	Manufacturer
1	Cryostat	Janis ST-500	Janis Research Company
2	Objective	NT56-982	Edmund Optics
3	Beam splitter	BS017	Thorlabs
4	Lens	ACN127-020-B	Thorlabs
5	Spectrometer	iHR550 Imaging Spectrometer	Horiba Scientific
9	Camera	InGaAs Spectroscopy CCD	Andor Technology

Table 4: Lab setup optical components

2.3 Pumping wavelength

Pumping light needs to have enough energy to fill all available states in the crystal lattice, in order to detect defects and impurities. For silicon, which has a bandgap of around 1.1eV, has most impurity/defect bands below the bandgap. In order to fill these states, the pumping wavelength should be below 1125nm, which corresponds to energies just over 1.1eV.

Silicon has different absorption lengths for different wavelengths. For 1125nm, the absorption depth is nearly 200 μm [38]. Compared to absorption for 532nm, 1125nm reach 200 times deeper into the sample.

Absorption length of about 1 μm for 532 nm laser, means that iron precipitates deeper in the sample won't be detected [25]. This limitation might be overcome by an excitation laser with a longer wavelength and absorption length in silicon. [2] report that small angle grain boundaries in multicrystalline silicon of 1° - 1.5° show D3 and D4 lines, while 2° - 2.5° show D1 and D2 lines. Comparing to data from electron beam induced current measurements show D1 and D2 lines to be correlated with shallow levels, while D3 and D4 appear in both shallow and deep levels [2].

A pumping wavelength of 800 nm is chosen for excitation. This corresponds to an absorption depth of 12 μm in silicon. With a larger wavelength, it would be invisible to the naked eye, and make it much more difficult to align the setup, and make sure nothing is blocking the pathway. In the case of an imperfect filter in front of the spectrometer, 800nm (1.55eV) and the second order diffraction maxima at 1600 nm (0.775 eV) would be outside the most interesting wavelengths from silicon luminescence (see table 5).

2.4 Spot size

Having a small diameter on the pumping laser allows for a high resolution of characteristics on the sample. In an iron contaminated sample, [25] show

that at some distinct spots of a size between $1\mu\text{m}$ and $4\mu\text{m}$, the band to band photoluminescence peak is particular low at spots with iron precipitates.

A large electron hole droplet could overshadow characteristics from impurities in the sample. [31] show that electron hole droplets become more intense for a smaller volume, with a silicon nanolayer smaller than the absorption depth of the laser. [31] used a 488nm pumping laser with $1.5\mu\text{m}$ diameter, on silicon nanolayer thickness of 50nm and 340nm. For the 50nm layer, [31] observed a large electron hole droplet, even for small pumping intensities, with the same amount of photo excited carriers per volume as for the 340nm layer. Assuming that a small volume give rise to a larger electron hole droplet, it would be a limiting factor for the spot size and pumping wavelength.

For the setup given here, the spot size is around $2\mu\text{m}$.

2.5 Laser intensity

With a large pumping intensity, an electron hole droplet become visible in the specter around 1.08eV in bulk silicon [39]. [31] show that electron hole droplets occur at weak excitations (0.75mW) and even at high temperatures for a silicon nanolayer of 50nm. For thickness of 340nm, the electron hole droplet show up at pumping intensity of 3mW and above, and the intensity of the electron hole droplet grow larger than for the free exciton at 15mW. This electron hole droplet is not wanted, as it can mask characteristic photoluminescence from impurities.

With a larger pumping intensity, the impurity photoluminescence would in some cases also increase. Photoluminescence from chromium bound with a boron atom is known to increase linearly with laser power [17, 18], and would be easier to detect at a higher pumping intensity.

2.6 Expected results

2.6.1 Phosphorus and boron doped samples

With fairly high concentrations of doping atoms, it's expected that they show up as separate lines in the photoluminescence spectra. [12] observe a line around 1.0924eV which is attributed to B^{TO} . Concentrations values for B in [12] are $6 * 10^{16} \text{ cm}^{-3}$. Also observed is a phosphorus line at 1.0916eV, with $8 * 10^{16} \text{ cm}^{-3}$ phosphorus atoms. ES1 and MH2 have similar B and P values, and is expected to show the same behavior. (See figure 27 and 28 in appendix 3.3.4)

There is a photoluminescence line involving carbon bound to oxygen in Czochralski silicon known as the C-O band [16]. In [40], it was observed only in crucible grown silicon, but not in float zone. In the crucible grown silicon, the oxygen impurities were $2 \cdot 10^{18}$ atoms/cm³, which is over ten times more than in ES1 and MH2. This makes it unlikely that any C-O complex luminescence will be strong enough to be detectable in these samples.

Another line involving carbon, is the two-carbon atom band [16]. This band has been detected in float-zone silicon with $C = 9.7 \cdot 10^{16}$ cm⁻³ after irradiation, together with the C-O complex line. The relative intensity between the C-O band and the two-carbon atom band in [16] show that the 969 meV band is close to 5 times larger than the 789 meV band. With both MH2 and ES1 having carbon impurities around $6 \cdot 10^{17}$ cm⁻³ it is possible that this line at 969 meV will be visible.

As for aluminum, [12] show a line at 1.09 eV called Al^{TO} in a sample with $2 \cdot 10^{16}$ cm⁻³ Al doping atoms. In ES1 and MH2, the Al impurities are 20 times less. In addition to a fairly low value of Al impurities, the Al^{TO} line is very close to the I^{TO}, which can make it difficult to detect, and not likely to show up in the results.

Fe bound with boron is also known to give rise to photoluminescence [23]. The sample used in the article had 10^{13} to 10^{16} cm⁻³ boron doping concentration. The article doesn't mention how many Fe impurity atoms that's introduced into the sample, but it's done by high temperature diffusion, and assumed to be considerably larger than for all the samples in this study.

Based on the low values of Fe impurities in these samples, it's assumed that interstitial Fe won't have any effect on the photoluminescence bands. The same goes for Ti, which also have a very low amount present.

2.6.2 Sample with added Chromium

This sample have the same impurity values as ES1, except for chromium. The closest comparison is samples used in [17]. Here, luminescence spectra was observed for chromium in an p-type sample. Interstitial chromium concentrations were between 10^{14} and 10^{16} atoms/cm⁻³ in [17].

Chromium in an n-type sample doped with phosphorus atoms does not result in any luminescence, but chromium bound with boron show a clear line at 0.8432eV (CrB⁰). The reaction velocity for the formation of CrB pairs at room temperature depend on the boron concentration. For large (10^{15} cm⁻³) boron content, the chromium-boron reaction reach saturation in less than a day after chromium diffusion [17].

MH2 are neither n og p-type, however there is enough boron atoms to

saturate chromium by forming CrB pairs. Chromium atoms are in the order of 10^{14} atoms/cm³ which is similar to that in [17]. Expected photoluminescence spectra is therefor expected to be similar. (See figure 31 in appendix). With most of the boron bound with chromium, it is likely that the boron lines will be severely reduced compared to ES1, and not detectable. There are also Fe impurities present in the sample, that can form bonds with boron. Based on the low amount of Fe in this sample, those bonds are not believed to have any impact on the photoluminescence.

2.6.3 Sample from clean feedstock

Having carbon values around $2.26 \cdot 10^{17}$, it is possible that the two-carbon atom band is visible here also. Else this sample is expected to only show intrinsic values similar to [12] in so called "‘good'" areas due to low concentration of impurities. However, there might be precipitates and higher concentration of impurities at the grain boundaries and dislocations. Particularly heavy metals like Fe and Al can be detected here. It is expected that the band to band recombination from silicon show considerably lower intensity for these areas.

2.7 Results plotting

In order to plot the results from the spectrometer, there are a few manipulations that's needed.

2.7.1 Disregarding defect pixels

By taking a spectra with the shutter closed, it is possible to measure the dark current coming from the camera. The dark current should be equally distributed across the pixels, based on the assumption that all pixels behave the same. For long integration time, this is not the case:

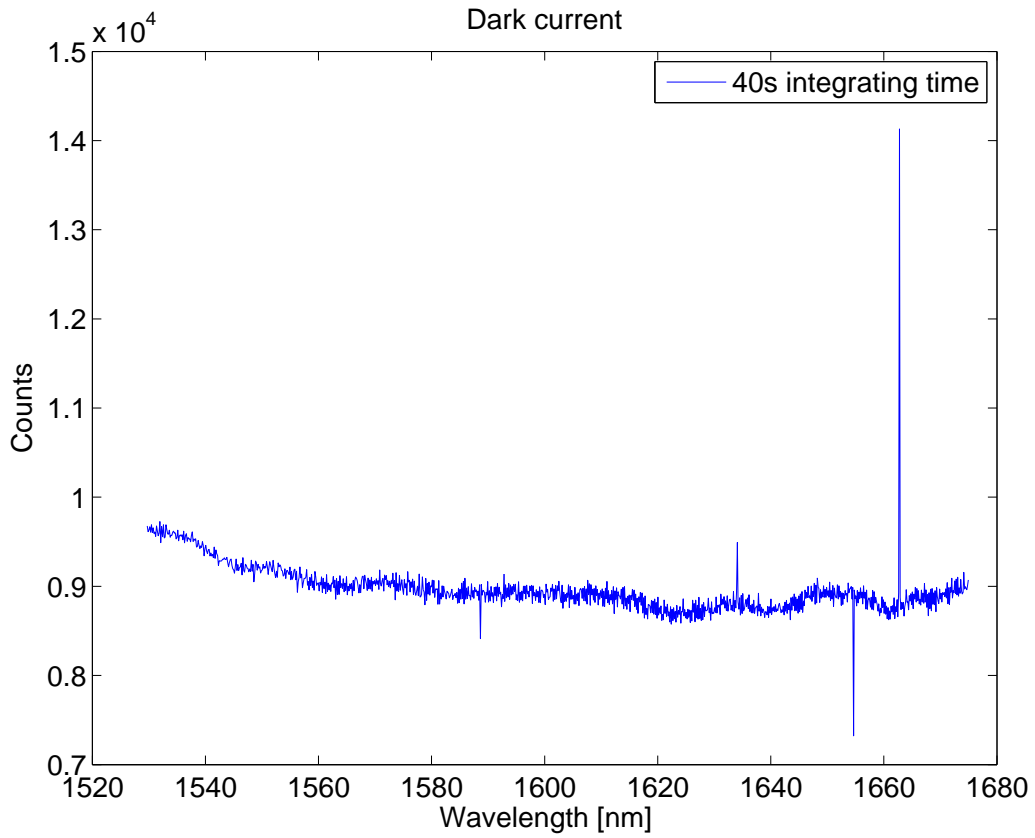


Figure 3: Dark current signal from the camera with defective pixels with shutter closed, and CCD at -75°C using a random center wavelength

To solve this problem, the four pixels are disregarded, and the value of the neighbor pixel has been used instead. Matlab code for this is available in the appendix. Comparing the before and after clearly show how this is done:

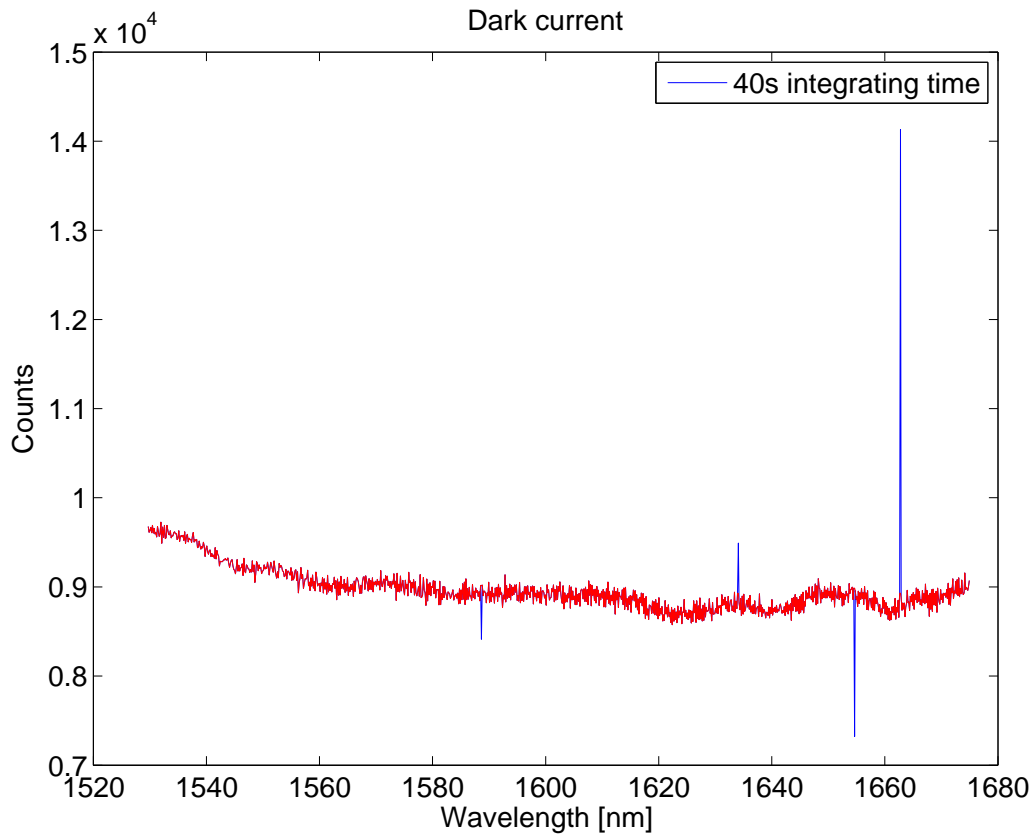


Figure 4: Dark current signal from the camera with defective pixel correction in red using a random center wavelength

The defective pixels are less apparent for shorter integration time, but still a problem:

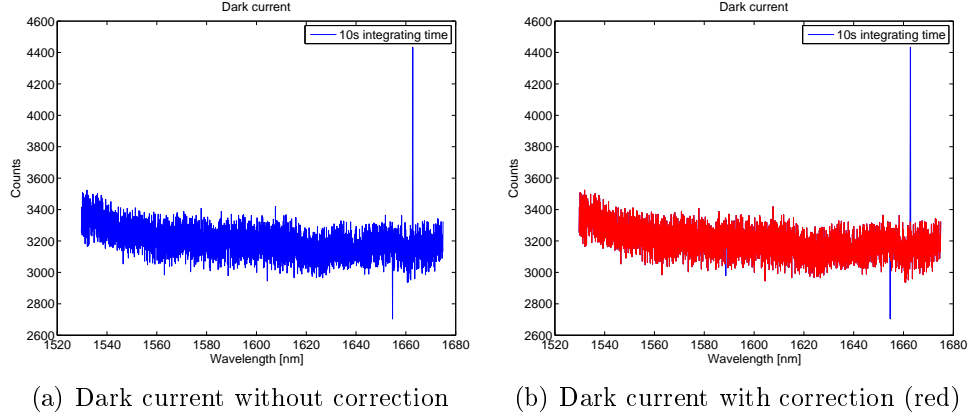


Figure 5: Dark current with 10s integration time using a random center wavelength

Dead pixel correction is performed in all results.

2.7.2 Noise reduction

As seen in the previous section, there is a dark current signal present. Ideally, all pixels should behave exactly the same, and give an exact dark current offset to subtract. This is not the case. The dark current is unevenly distributed over the pixel array, and needs to be measured by itself in order to remove it. The dark current noise shape is fairly static, with some white noise elements on top, but the shape is nearly identical from one measurement to the other with the CCD at a constant temperature.

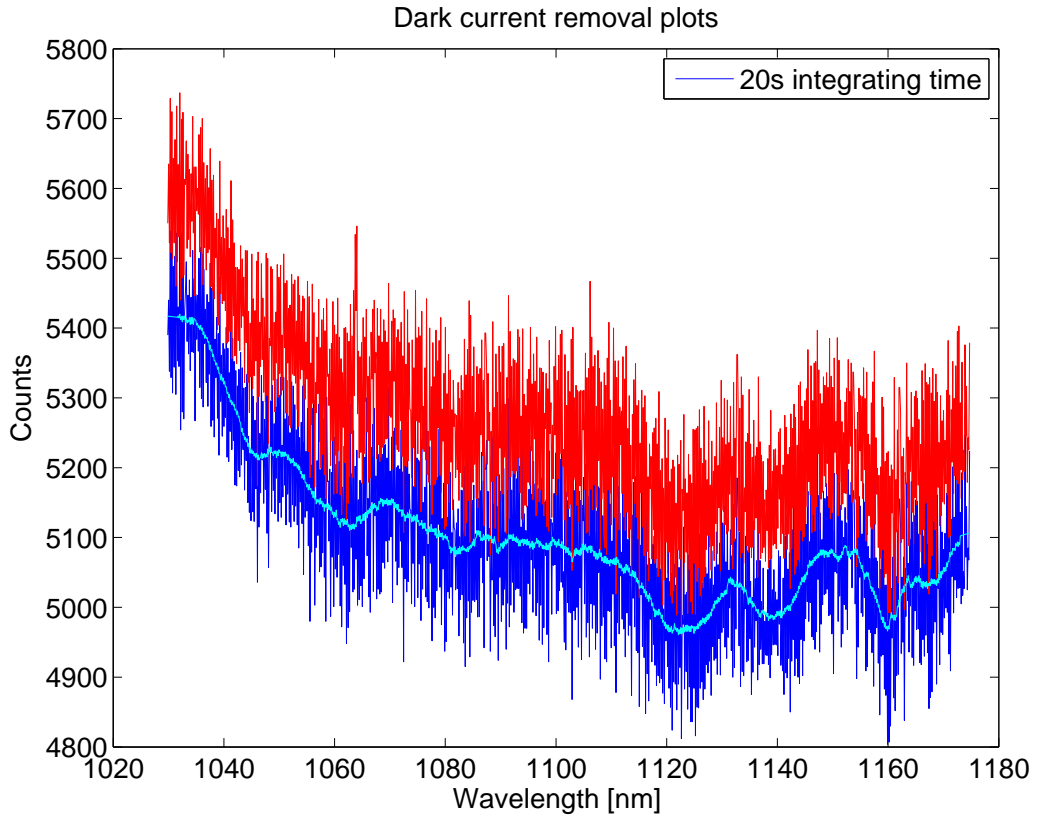


Figure 6: Dark current (blue) and dark current + background noise (red) with filtered noise floor estimation (cyan)

By subtracting the offset found in the dark current noise measurement, only background noise should be present. The matlab code used to do this can be found in the appendix.

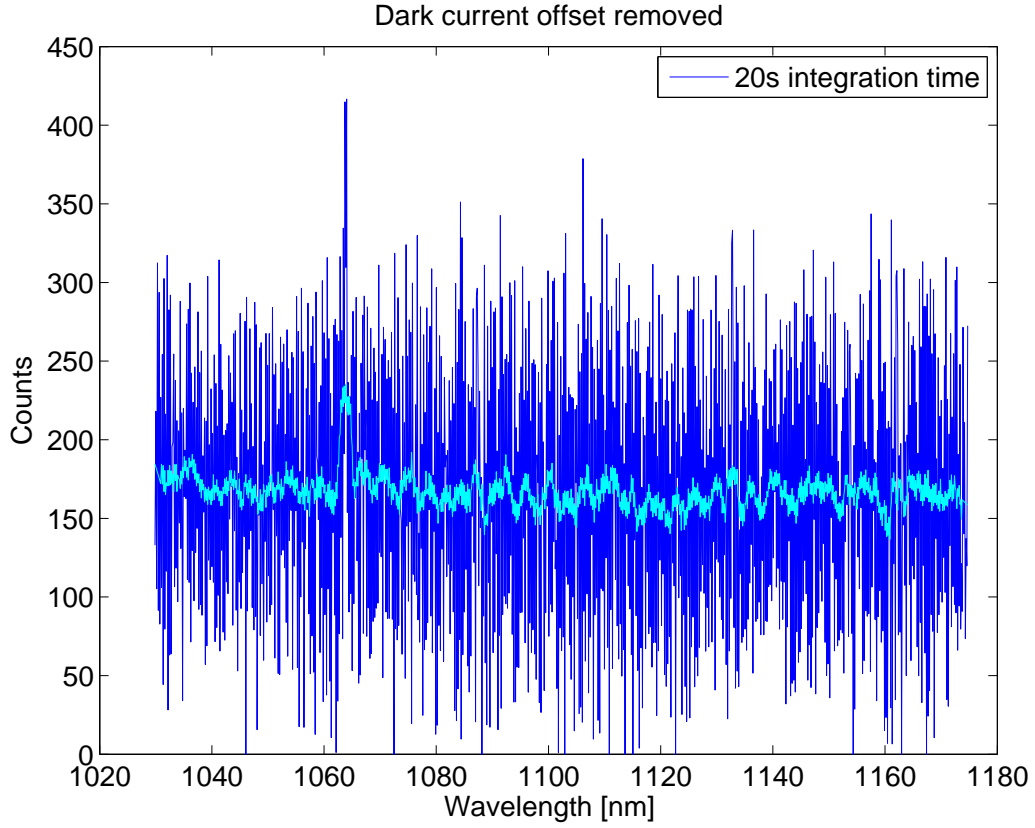


Figure 7: Dark current removed from background noise (blue), and filtered signal (cyan)

It appears that the dark current noise is larger with the shutter open, compared to closed. But a more critical noise in the spectrum is a background signal around 1064nm. The spectrometer has a range of 140nm when using 300 as grating. It has proven difficult to align the system so that the entire array of pixels in the camera get an equally distributed light beam. And based on the noise level, the nm interval is chosen as 100nm, in order to remove the left hand side of the spectra when gluing different intervals together. This also avoid the problem of not hitting the entire array evenly. To get a full overview over the background noise, a full spectra was done, and glued together. This full spectra show that the artifact visible in 7 is the only background noise line visible in the wavelength area 800-1650nm.

3 Results

Results have been corrected for dead pixels, measured dark current, and measured background noise unless otherwise specified. Grating is fixed at 300, and pumping wavelength is 800nm. Counts is a number given from the spectrometer which relate to the relative intensity detected by the pixel in the CCD.

3.1 R6-Q3-210

This is the electronic grade sample, with a very low amount of impurities.

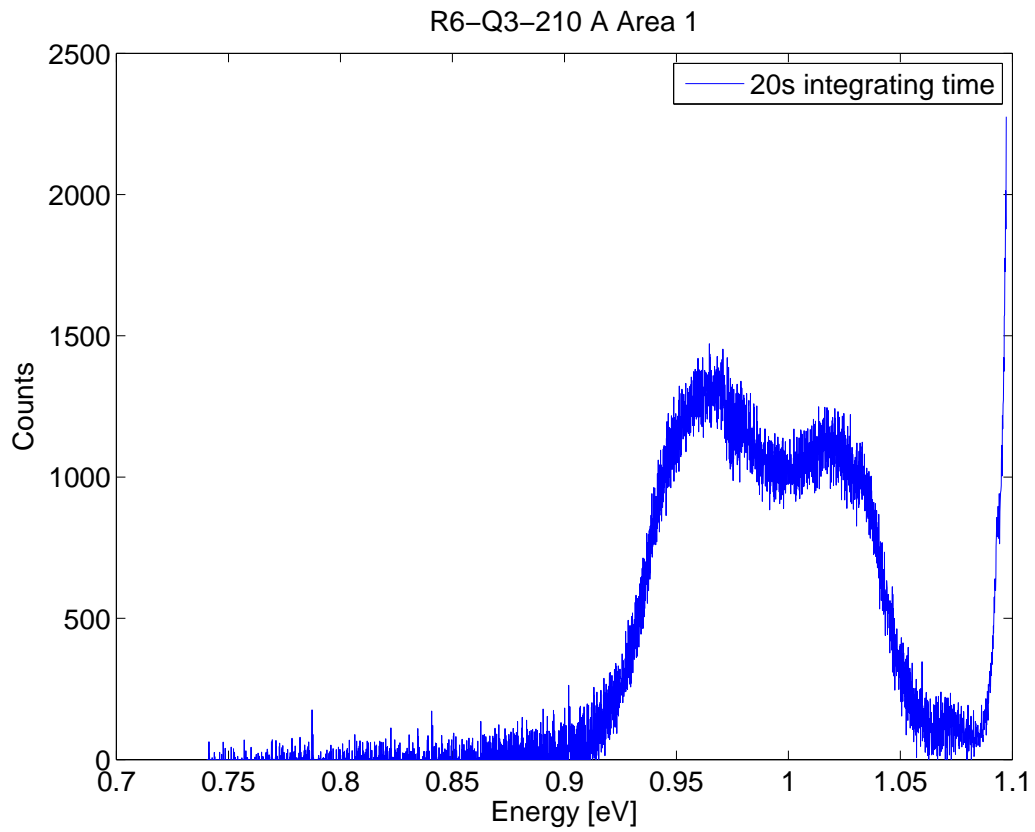


Figure 8: Sample R6-Q3-210 A pumped with 170mW at 10K in a dislocation line (Area 1).

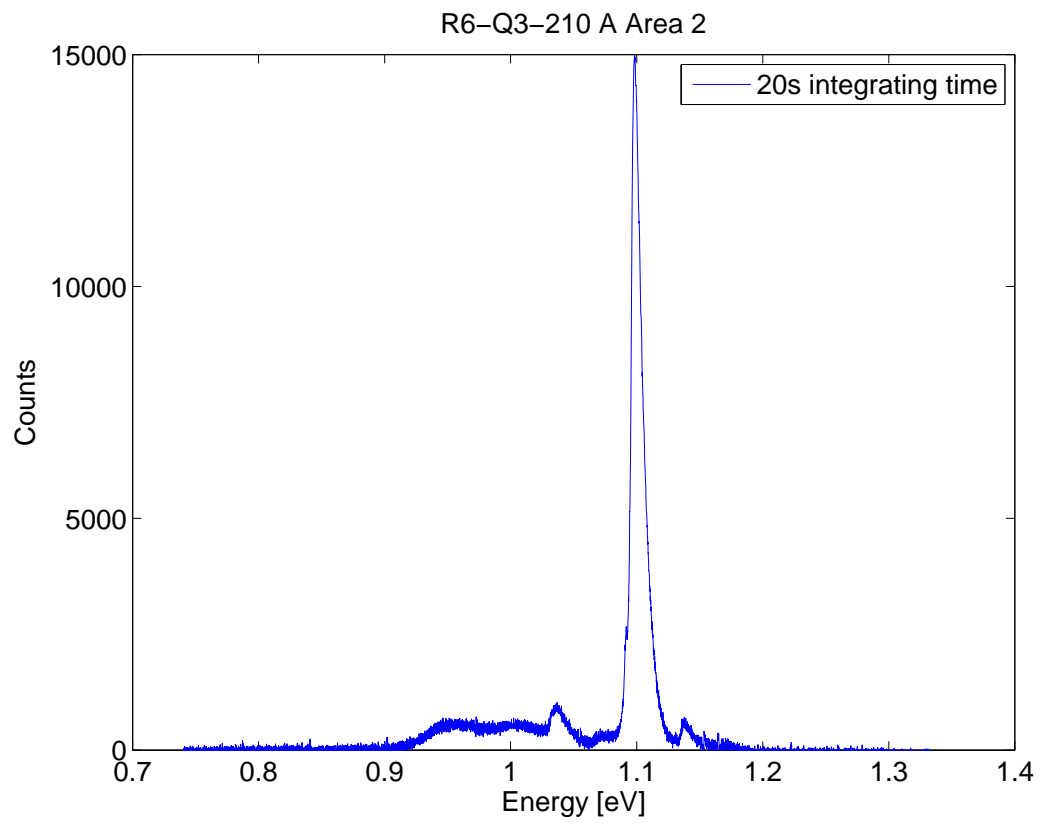


Figure 9: Sample R6-Q3-210 A pumped with 170mW at 10K in a dislocation dot (Area 2).

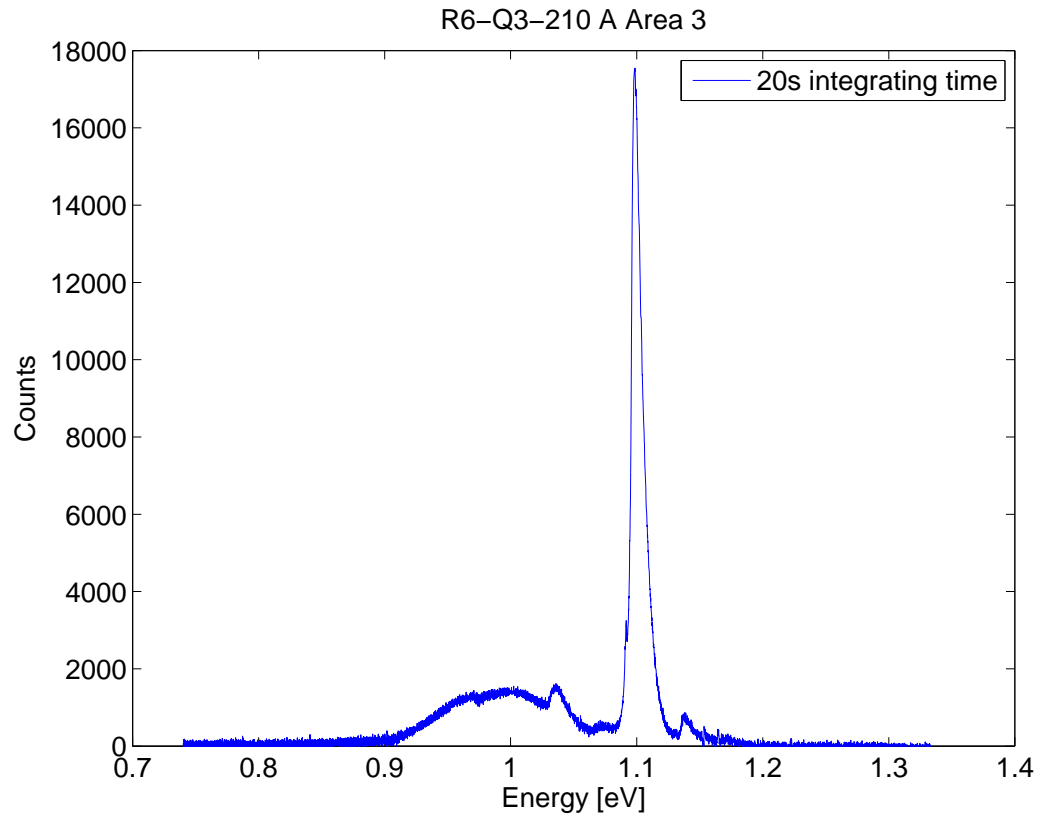


Figure 10: Sample R6-Q3-210 A pumped with 170mW at 10K in a dislocation free area (Area 3).

3.2 ES1-Q3-201

This sample is from a dirty feedstock, with large amount of P and B.

3.2.1 Room temperature

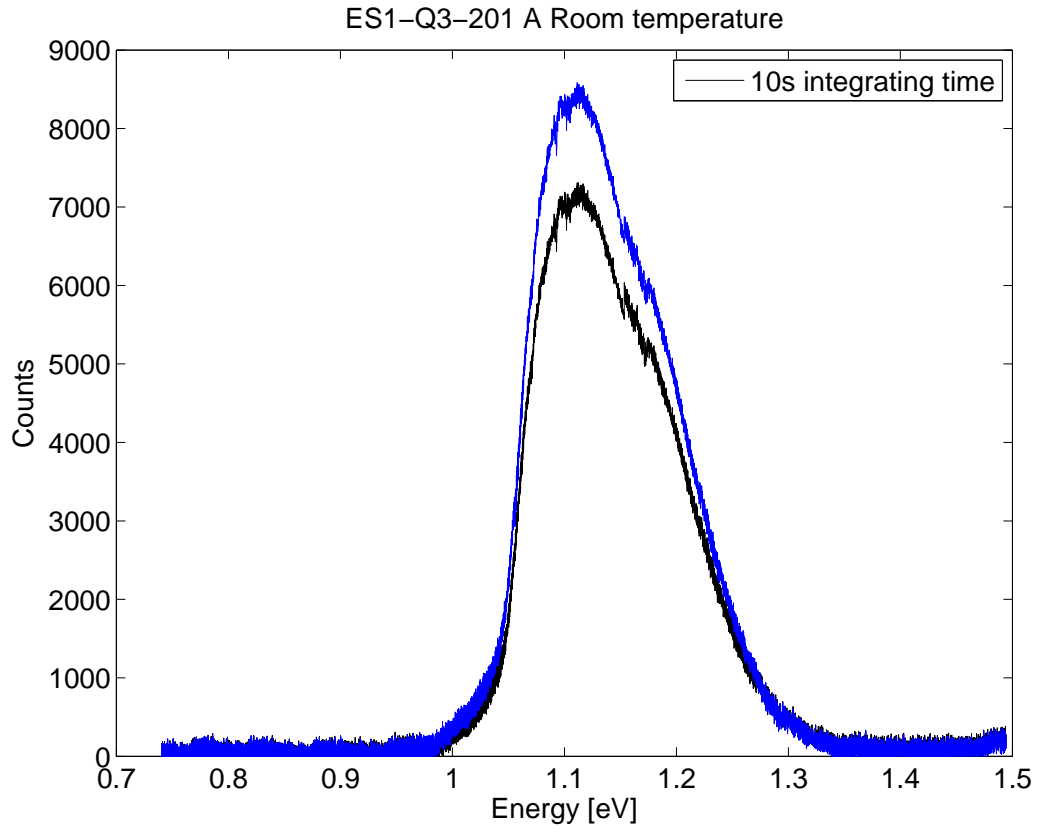


Figure 11: Sample ES1-Q3-201 A pumped with 26mW at 295K in a dislocation line (black) and in a clean area (blue). An estimated dark current offset has been subtracted.

3.2.2 Low temperature

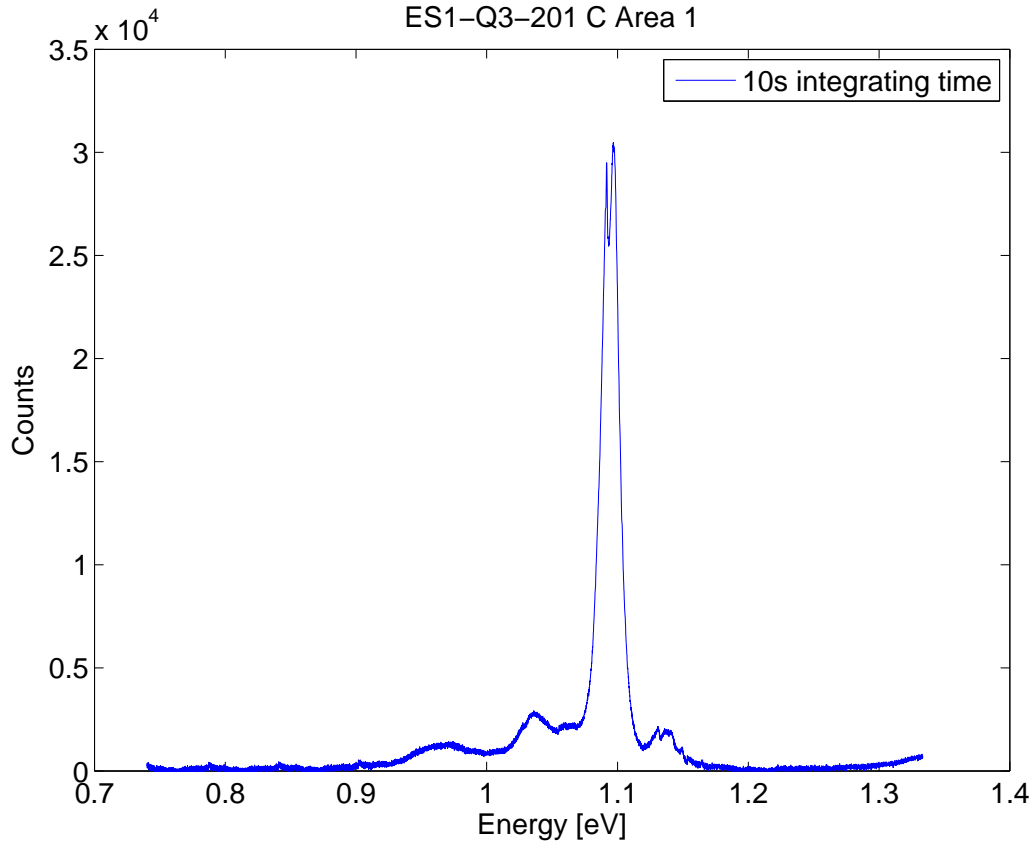


Figure 12: Sample ES1-Q3-201 C pumped with 170mW at 12K in a dislocation free area (Area 1).

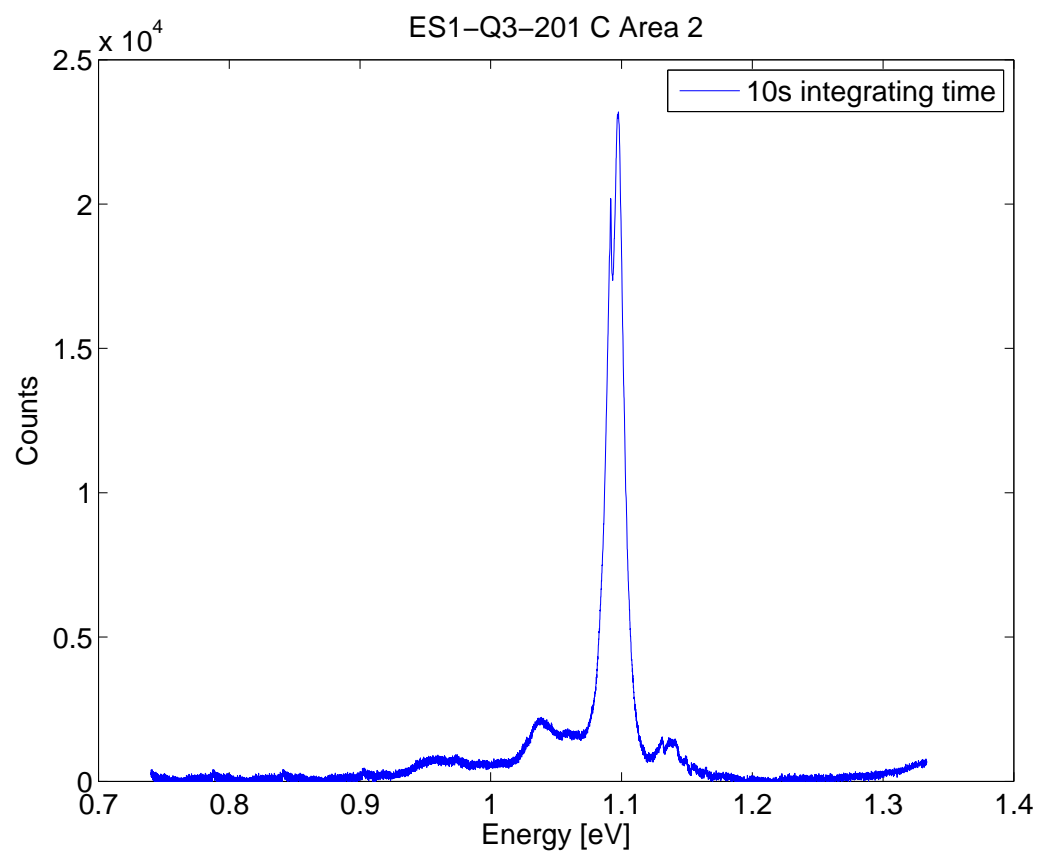


Figure 13: Sample ES1-Q3-201 C pumped with 170mW at 12K in a dislocation spot (Area 2).

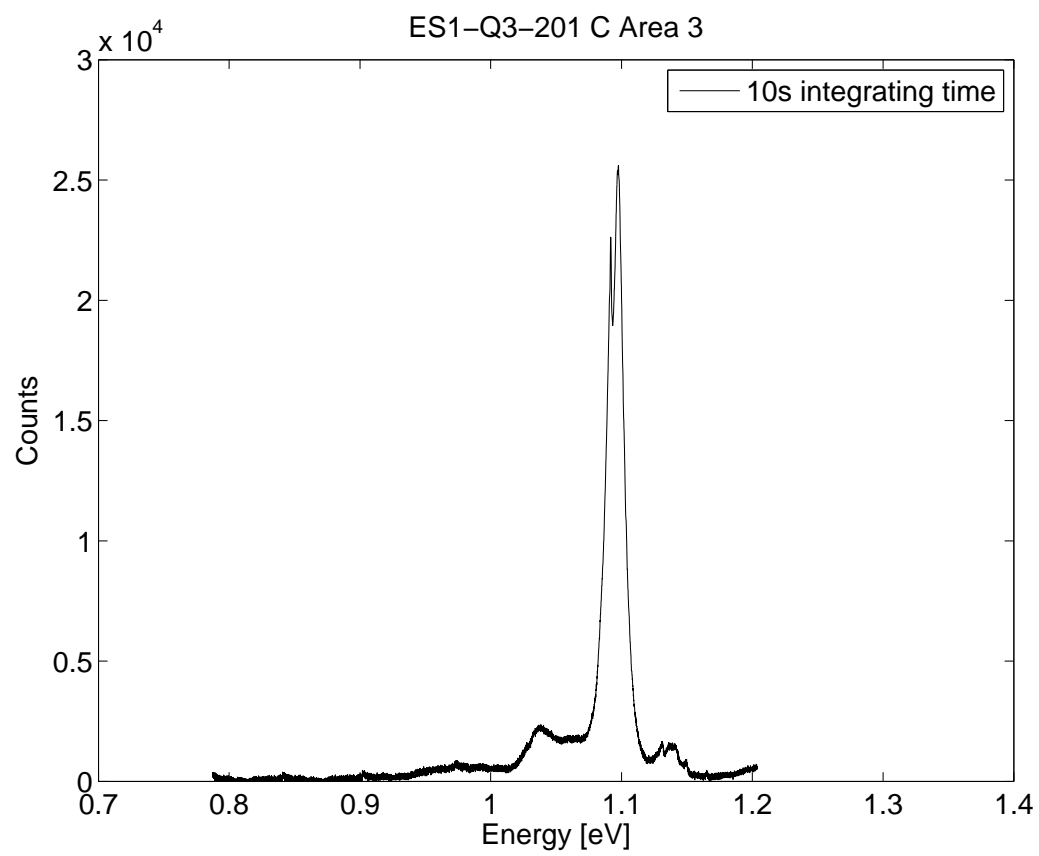


Figure 14: Sample ES1-Q3-201 C pumped with 170mW at 12K in a grain boundary (Area 3).

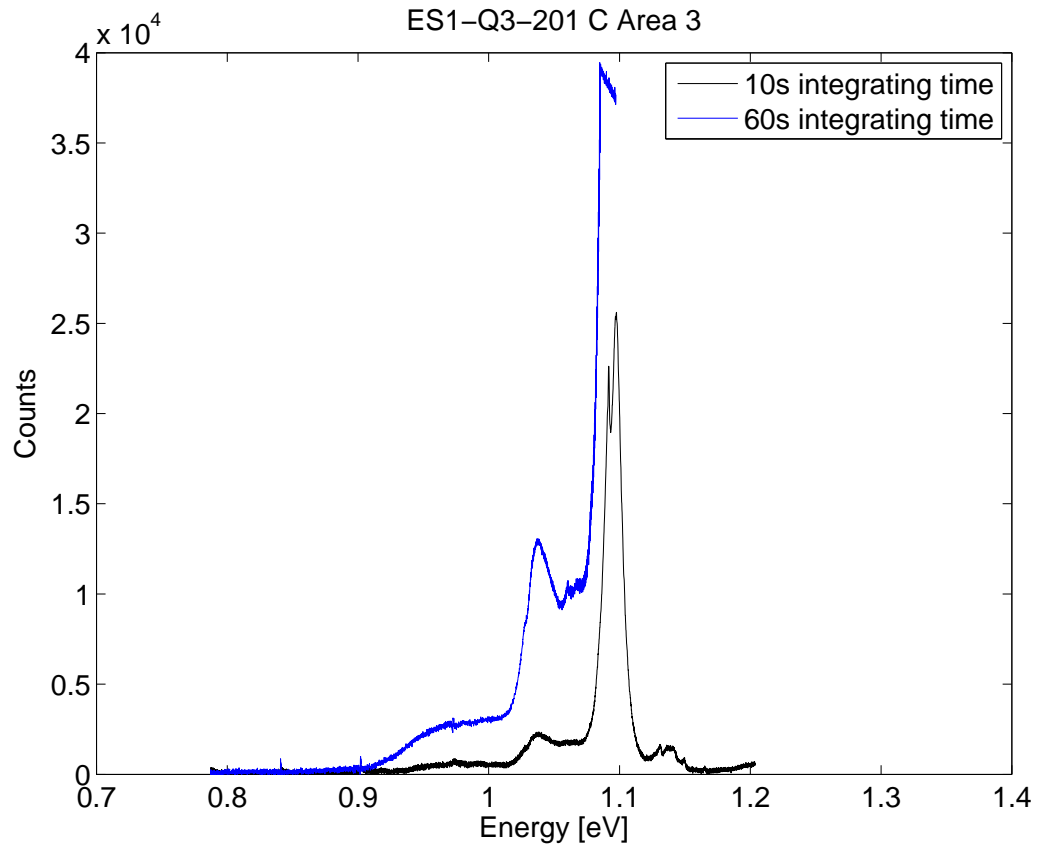


Figure 15: Sample ES1-Q3-201 C pumped with 170mW at 12K in a grain boundary (Area 3) with the result in figure 14 plotted as the black line.

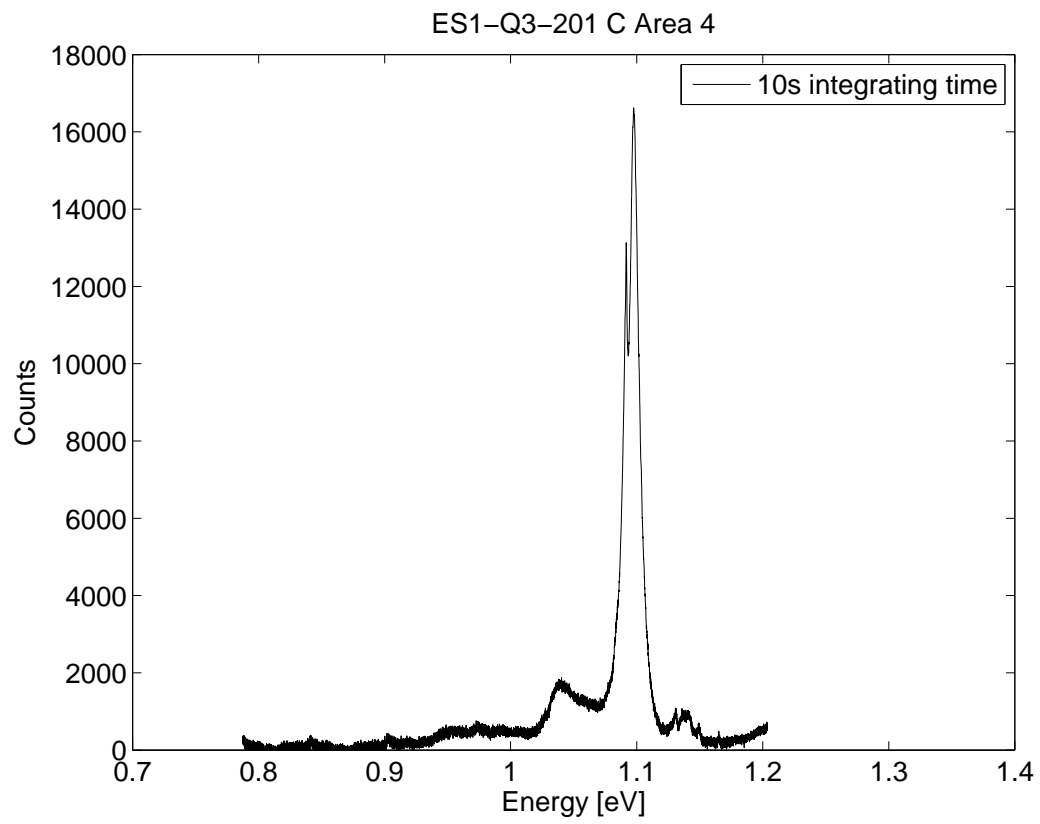


Figure 16: Sample ES1-Q3-201 C pumped with 170mW at 14K in a dislocation line (Area 4).

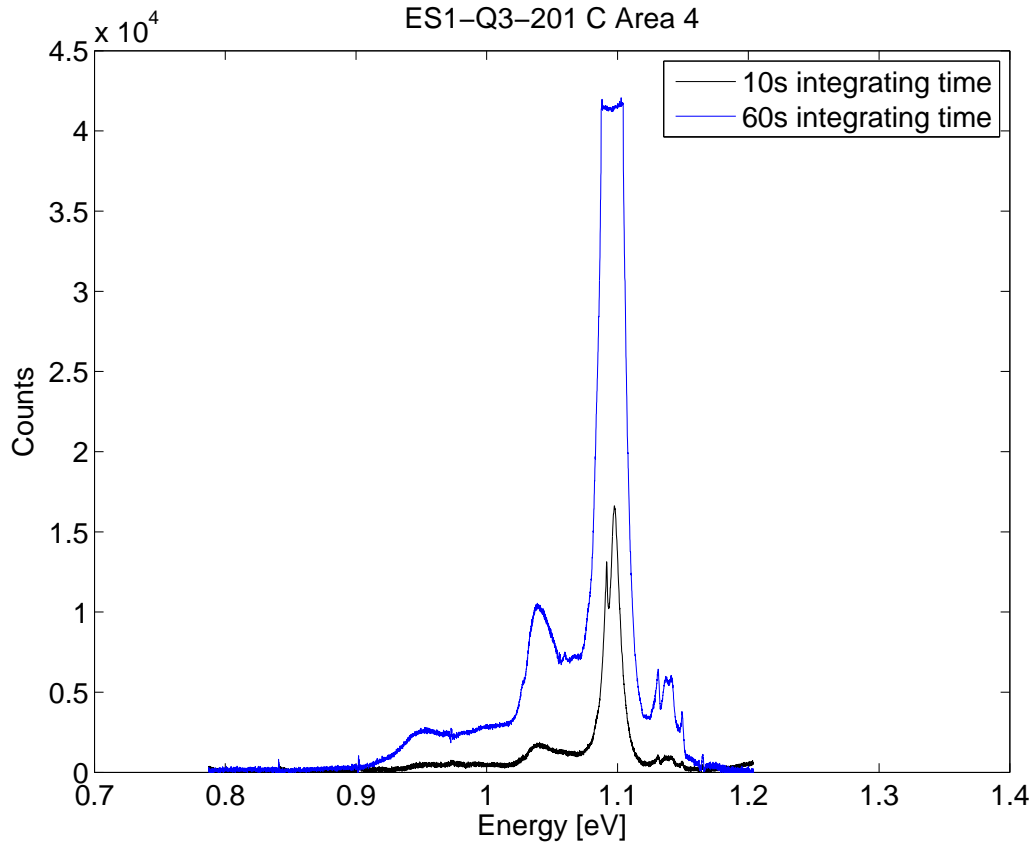


Figure 17: Sample ES1-Q3-201 C pumped with 170mW at 14K in a dislocation line (Area 4) with the result in figure 16 plotted as the black line. For 60s integration, the main TO line around 1.1eV is saturating the camera.

3.3 MH2-Q3-210

This sample is the same as ES1-Q3-201 except for added chromium in this one.

3.3.1 Room temperature

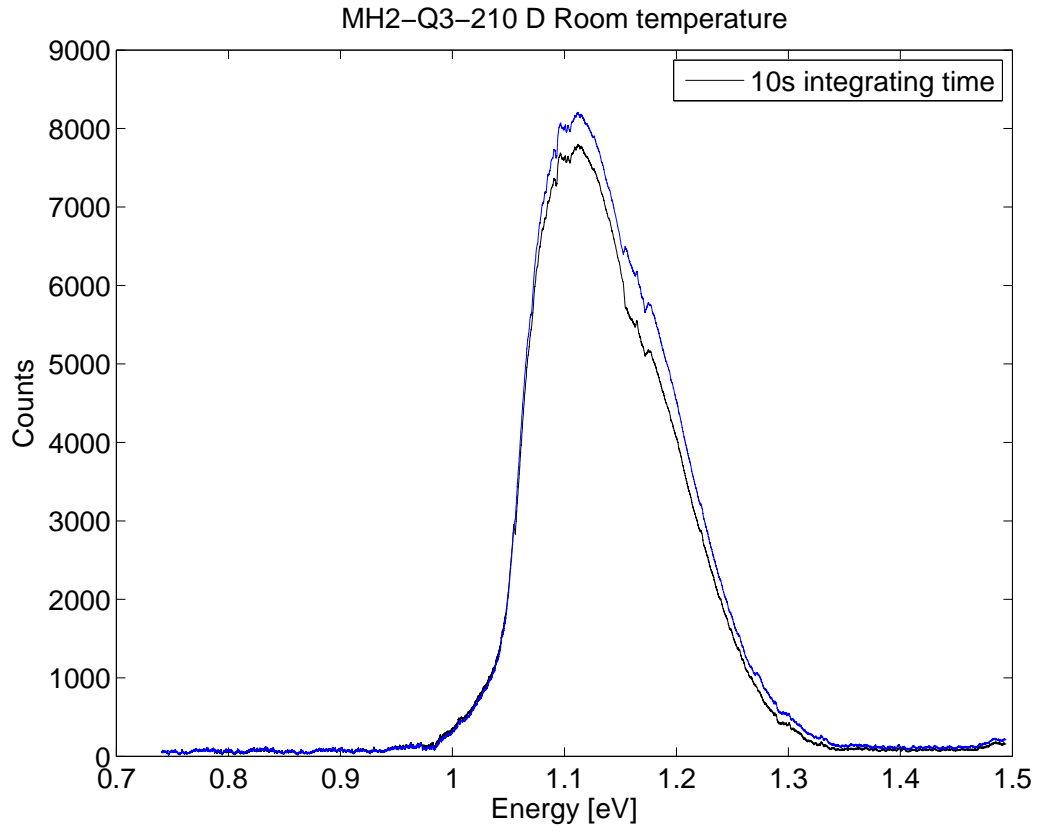


Figure 18: Sample MH2-Q3-210 C pumped with 26mW at 295K in a dislocation free area (blue), and in an area with dislocations (black). An estimated dark current offset has been subtracted, and results are Savitzky-Golay filtered for easier comparison.

3.3.2 At 70K

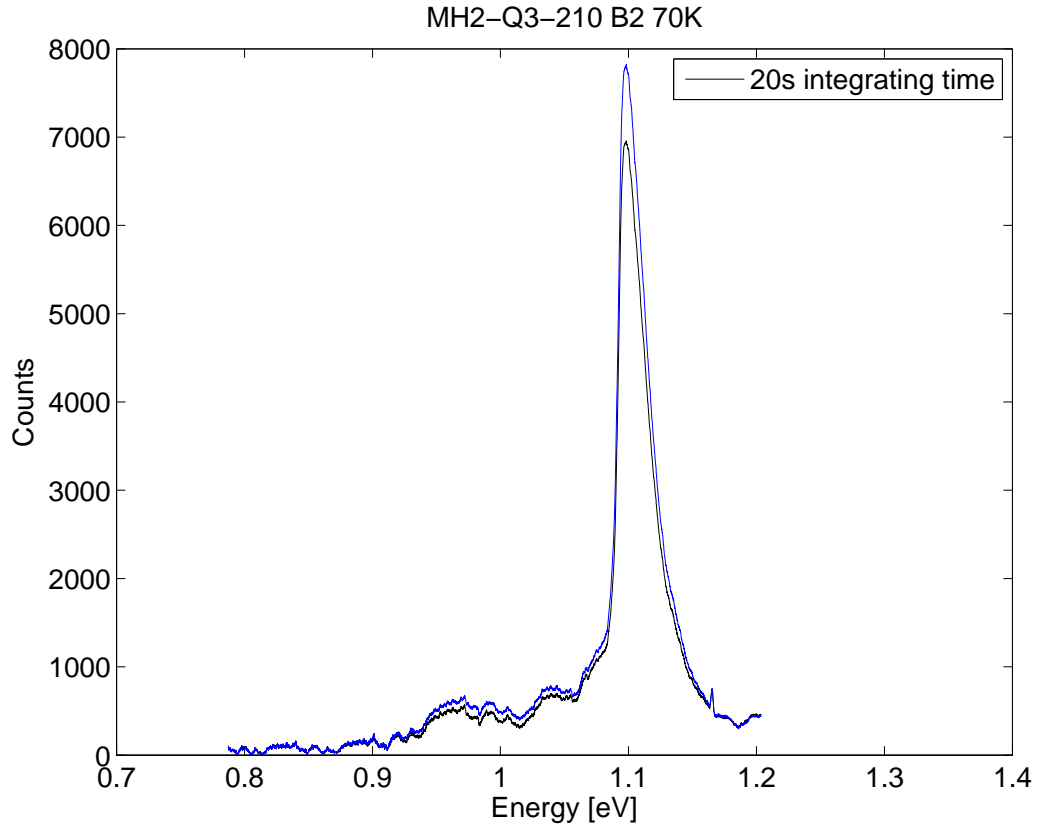


Figure 19: Sample MH2-Q3-210 D pumped with 170mW at 70K in a dislocation free area (blue), and in an area with dislocations (black). An estimated dark current offset has been subtracted, and results are Savitzky-Golay filtered for easier comparison.

3.3.3 Low temperature

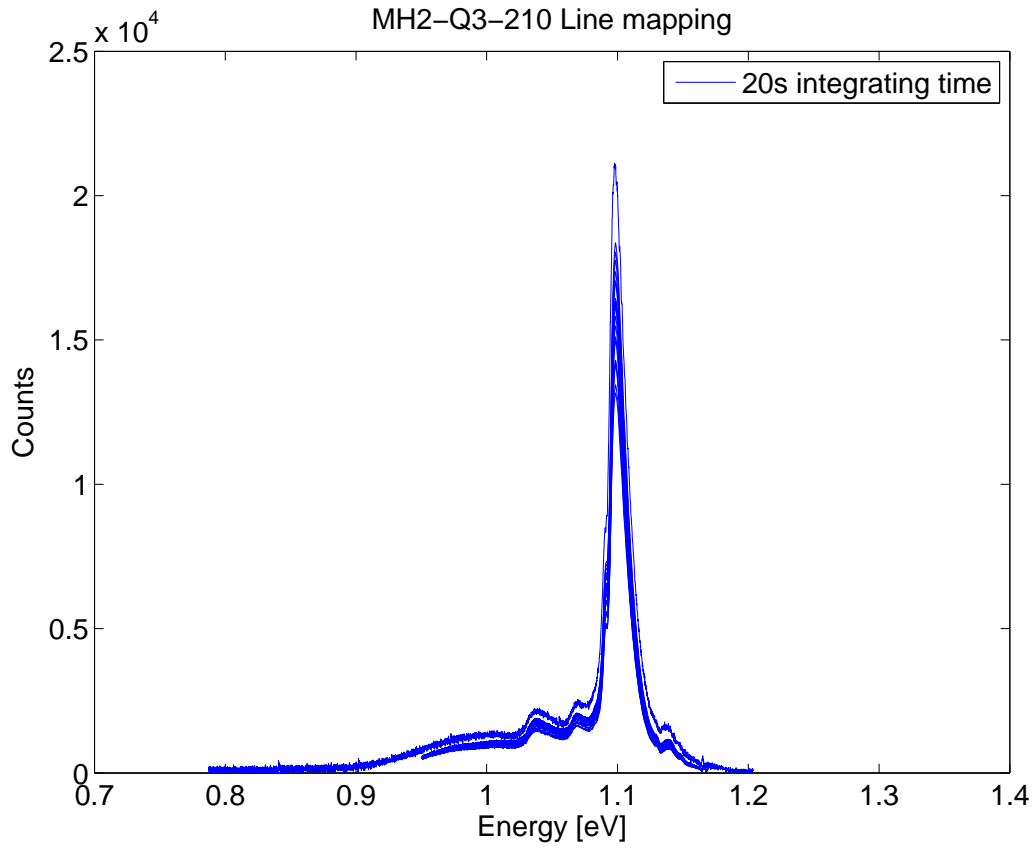


Figure 20: Sample MH2-Q3-210 B2 pumped with 170mW at 12K in a dislocation free area (Area 1).

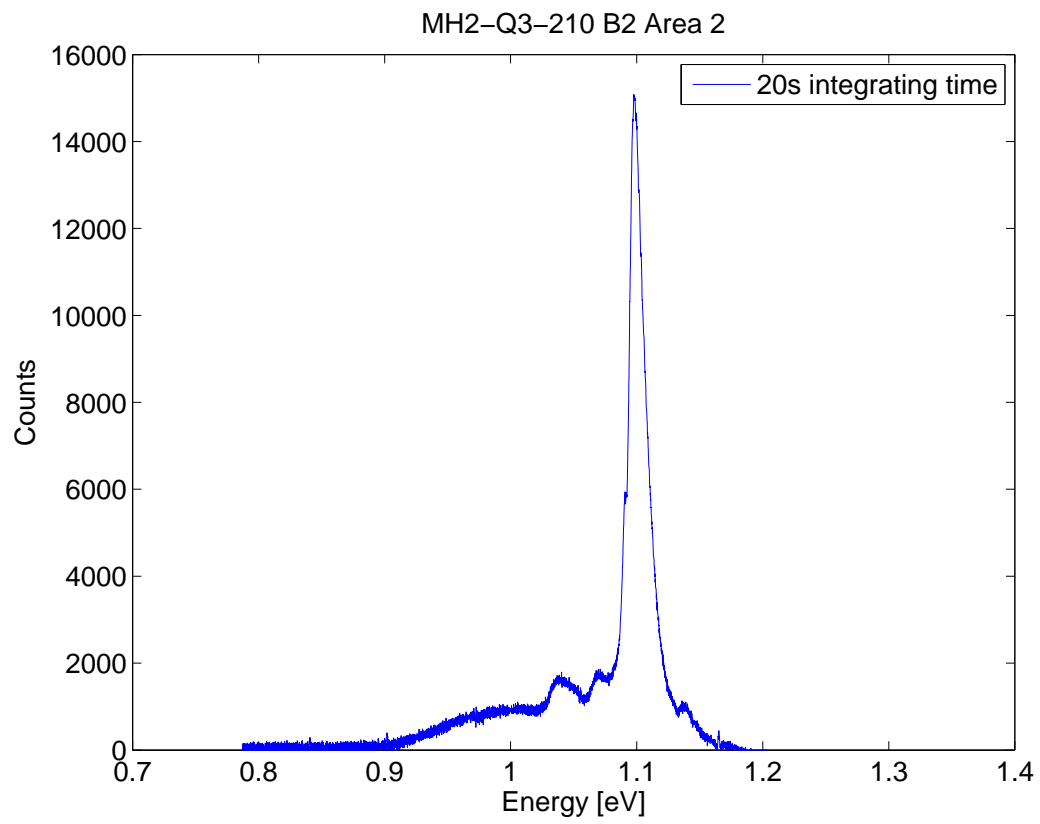


Figure 21: Sample MH2-Q3-210 B2 pumped with 170mW at 12K in a dislocation line (Area 2).

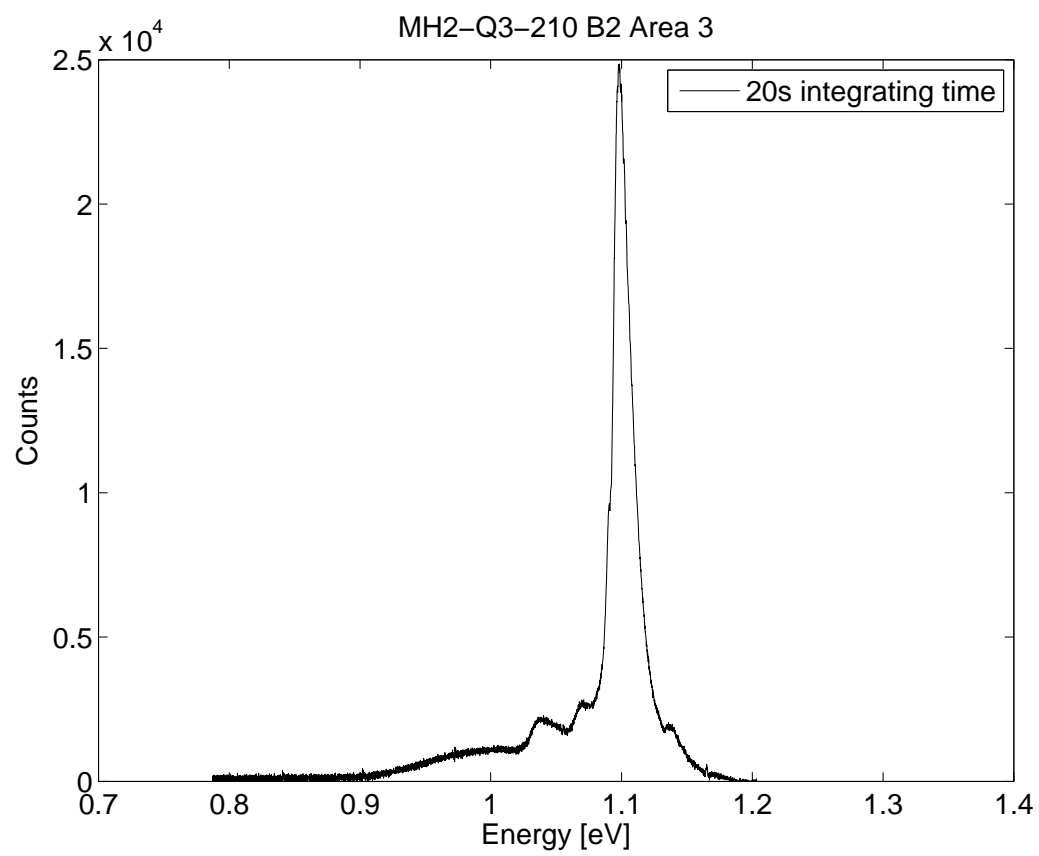


Figure 22: Sample MH2-Q3-210 B2 pumped with 170mW at 12K in a dislocation dot (Area 3).

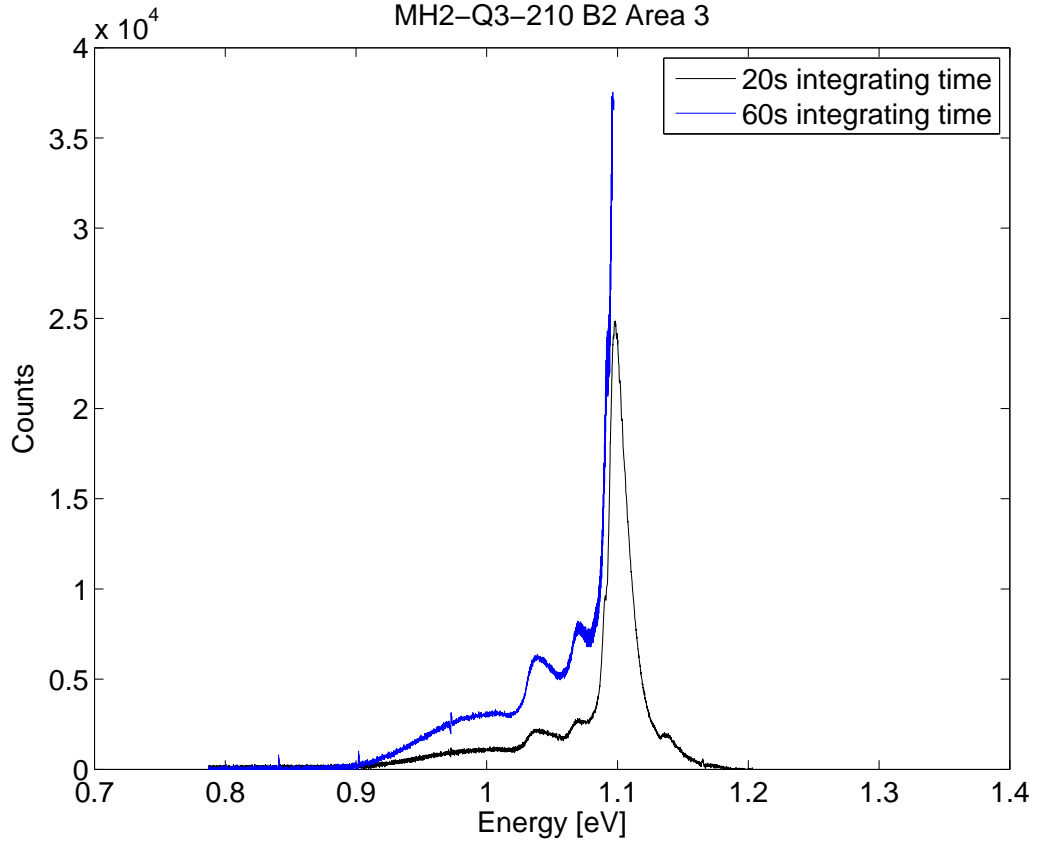


Figure 23: Sample MH2-Q3-210 B2 pumped with 170mW at 12K in a dislocation dot (Area 3) with 20s integration time (black) and 60s integration time (blue). The 60s integration time has an estimated dark current offset subtracted, in addition to measured dark current due to mismatched dark current measurement.

3.3.4 Line mapping

These results are a line mapping of different spots on the sample.

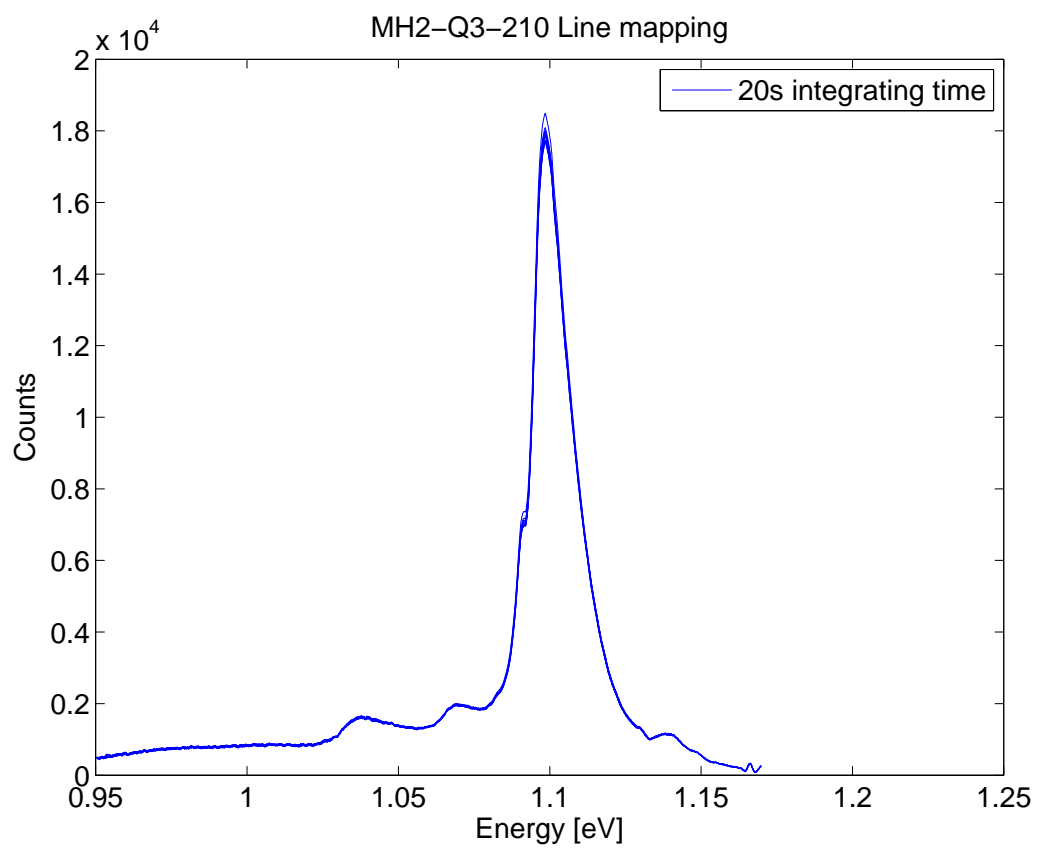


Figure 24: Sample MH2-Q3-210 B2 pumped with 170mW at 14K line map using 10 small steps.

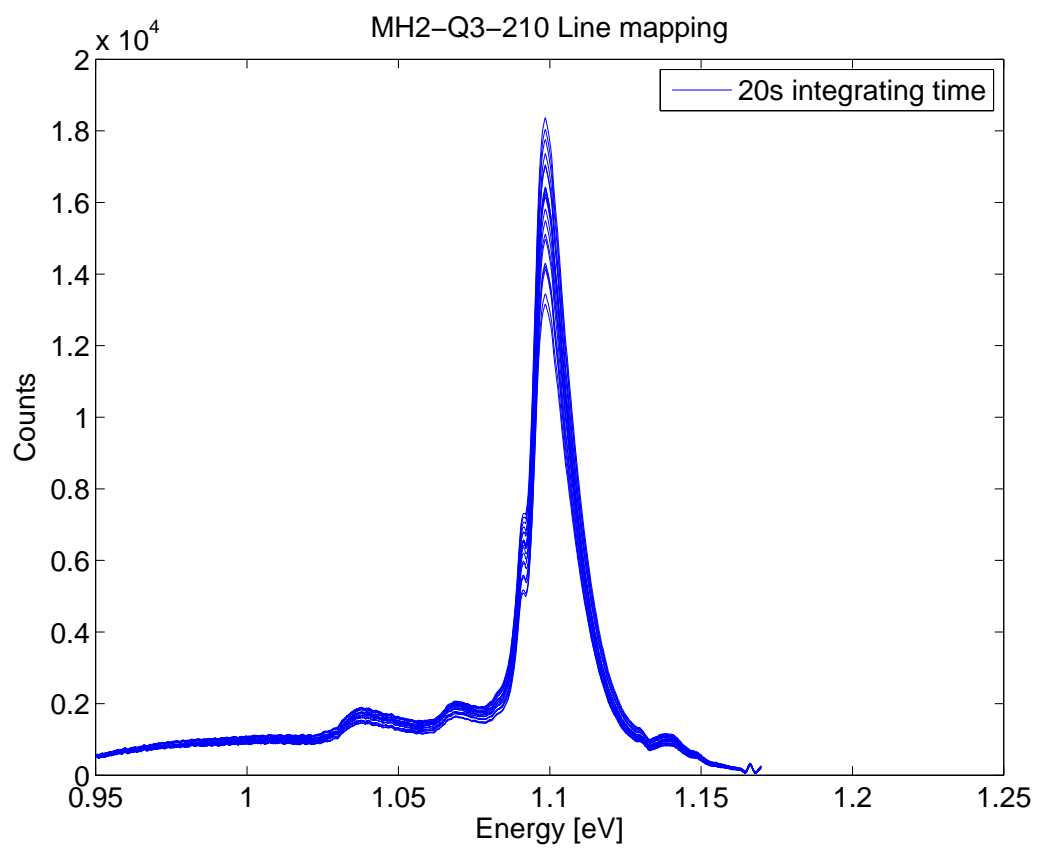


Figure 25: Sample MH2-Q3-210 B2 pumped with 170mW at 14K line map using 20 steps exactly 5 times larger than in figure 24.

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A Silicon energy bands

Energy	Name	Temp.	Impurity / Defect	Observed in
0.735eV	ZPL	22K	Fe contamination	[22]
0.745eV	C-N		Carbon-Nitrogen complex	[16]
0.76-0.8eV	Defect	290K	Dislocation with low contamination	[10, 13, 46]
0.77-0.78eV	D _b	4.2-295K	Oxygen impurity band	[33, 34]
0.77eV	P line	12K	C-O complex related	[16, 52]
0.780eV	CrB ^{0Γ}	4.2K	CrB ⁰ phonon replica	[18]
0.79eV	C-O	12K	Carbon-Oxygen complex	[16, 52, 40]
0.80eV	D1'	77K	Dislocations ¹	[10, 13]
0.812eV	D1	4.2K	Dislocation related line ¹	[1, 3, 51]
0.8160	CrB ²	4.2K	Cr-B excitation of local vibrations	[18]
0.8402	CrB ¹	4.2K	Cr-B excitation of local vibrations	[18]
0.8432eV	CrB ⁰	4.2K	Cr-B pair no-phonon	[17, 18]
0.875eV	C-Ga		Carbon-Gallium complex	[16]
0.875eV	D2	4.2K	Dislocation related line ¹	[1, 3, 51]
0.89eV	D2'	77K	Dislocations ¹	[10, 13]
0.8-0.9eV	D _{a1}	11K	Broad background emission under D1/D2	[33]
0.91eV	H-line	12K	C-O complex related	[16, 52]
0.93eV	H-line	12K	C-O complex related	[16, 52]
0.934eV	D3	4.2K	Dislocations ²	[1, 3, 51]
0.95eV	D3'	77K	Dislocations ²	[10, 13]
0.953eV	D5	4.2K	Straight dislocations	[3, 9]
0.9537eV	Defect	300K	Iron precipitate	[25]
0.968eV	I ^{TO+20Γ}	26K	TO + 2 Zone center phonon	[12]
0.969eV	C-C		Carbon-Carbon complex	[16]
0.98eV	R2BB	80K	Two phonon replica of band edge emission	[51]
0.9-1.0eV	D _{a2}	11K	Broad background emission under D3/D4	[33]
1.000eV	D4	4.2K	Dislocations ²	[1, 3, 51]
1.00eV	D4'	77K	Dislocations ²	[10, 13]
1.0089eV	FeB ⁰ (TO)	6K	Fe-B pair phonon replica	[23]
1.0126eV	D6	4.2K	Stacking faults	[3, 9]
1.013eV	I ^{TO+0Γ+IV^a}	26K	TO + 0Γ + IV ^a phonon	[12]
1.014eV	Cu ₀	4.2K	Copper doping	[21, 9]
1.018eV	W/I1		Radiation damage	[16]
1.0315eV	I ^{TO+0Γ}	26K	TO + Zone center phonon	[12]
1.04eV	R1BB	80K	One phonon replica of band edge emission	[51]
1.045eV	Q		4-Li atom complex	[16]
1.0504eV	FeB ²	6K	Fe-B pair contamination	[23]

Continued on next page

Table 5 – continued from previous page

Energy	Name	Temp.	Impurity / Defect	Observed in
1.051eV	I^{TO+IV^b}	26K	Inter valley phonon replica	[12]
1.0595eV	FeB^1	6K	Fe-B pair contamination	[23]
1.0692eV	FeB^0	6K	Fe-B pair no phonon	[23]
1.074eV	I^{TO+IV^a}	26K	Inter valley phonon replica	[12]
1.078	EHD	4.2K	Electron Hole Droplet dislocation-area	[30]
1.082eV	EHD_{TO}	4.2K	Electron Hole Droplet dislocation-free	[39, 30, 31]
1.0835eV	In^{TO}	30K	Indium doping TO	[12]
1.0888eV	Bi^{TO}	15K	Bismuth doping TO	[12]
1.0902eV	Al^{TO}	30K	Aluminum doping TO	[12]
1.0907eV	As^{TO}	15K	Arsenic doping TO	[12]
1.0907eV	Ga^{TO}	15K	Gallium doping TO	[12]
1.0916eV	P^{TO}	15K	Phosphorus doping TO	[12]
1.092eV	BE1	4.2K	Bound exciton	[1]
1.0921eV	Sb^{TO}	15K	Antimony doping TO	[12]
1.0970eV	I^{TO}/FE	26K	Transversal Optical/Free exciton	[12, 39, 30]
1.0924eV	B^{TO}	15K	Boron doping TO	[12]
1.093eV	B_{TO}	4.2K	TO phonon replica of Boron bound exciton	[14, 34]
1.1365eV	$I^{TA}/LO/FE$	26K	Transversal Acoustic/Longitudinal/FE	[39, 12]
1.1545eV	I^0	26K	No phonon	[12]
2.786eV	$^{48}_C Ti$	4.2K	C line Ti isotope 48 impurity in 6H SiC	[20]
2.820eV	$^{48}_B Ti$	4.2K	B ⁰ line Ti isotope 48 impurity in 6H SiC	[20, 54]
2.85eV	$^{48} Ti$	4.2K	Ti isotope 48 impurity in 4H SiC	[19]
2.861eV	$^{48}_A Ti$	4.2K	A ⁰ line Ti isotope 48 impurity in 6H SiC	[20, 54]

Table 5: Silicon energy bands

¹D1 and D2: It has been argued that they originate in electronic transition at the geometrical kinks on dislocations [5], point defects [3] and impurities [6] and/or from the reaction products of dislocations [7].

²D3 and D4 lines is generally thought to be related to electronic transition within dislocation cores [8]. In addition, it has been suggested that the D3 line most likely is a phonon-assisted replica of D4 [8].

B Sample types and procedures

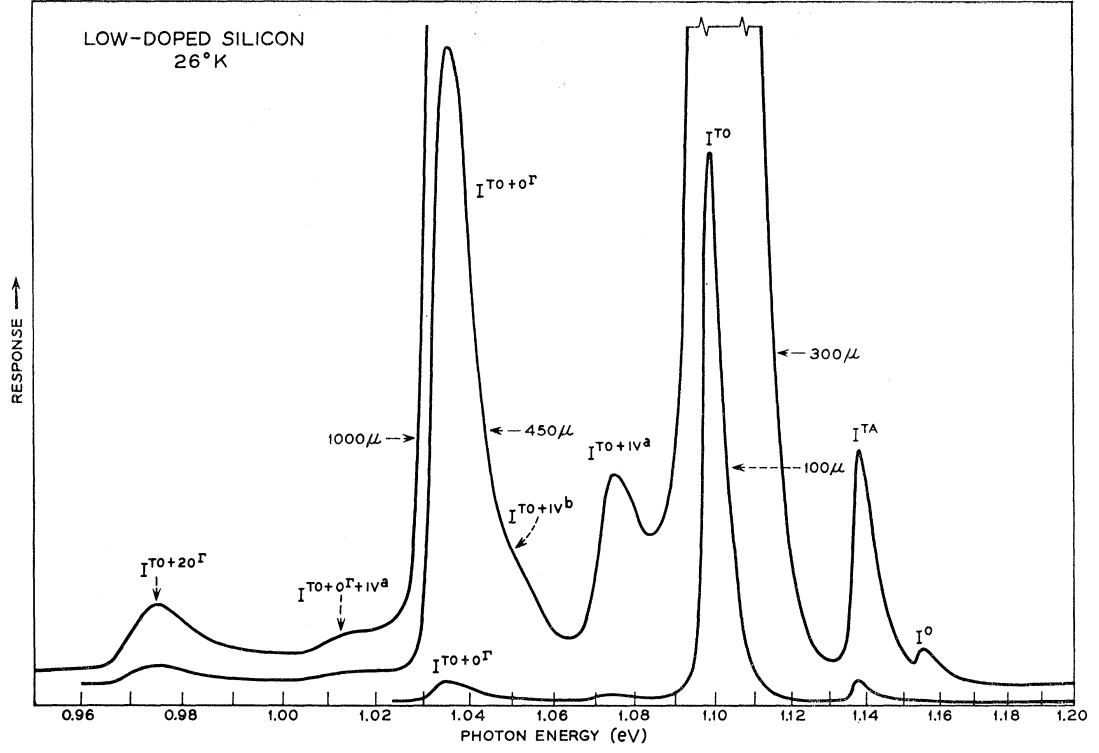


Figure 26: Intrinsic/low doped ($2 \cdot 10^{14} \text{ cm}^{-3}$ P atoms) Si PL specter from [12]

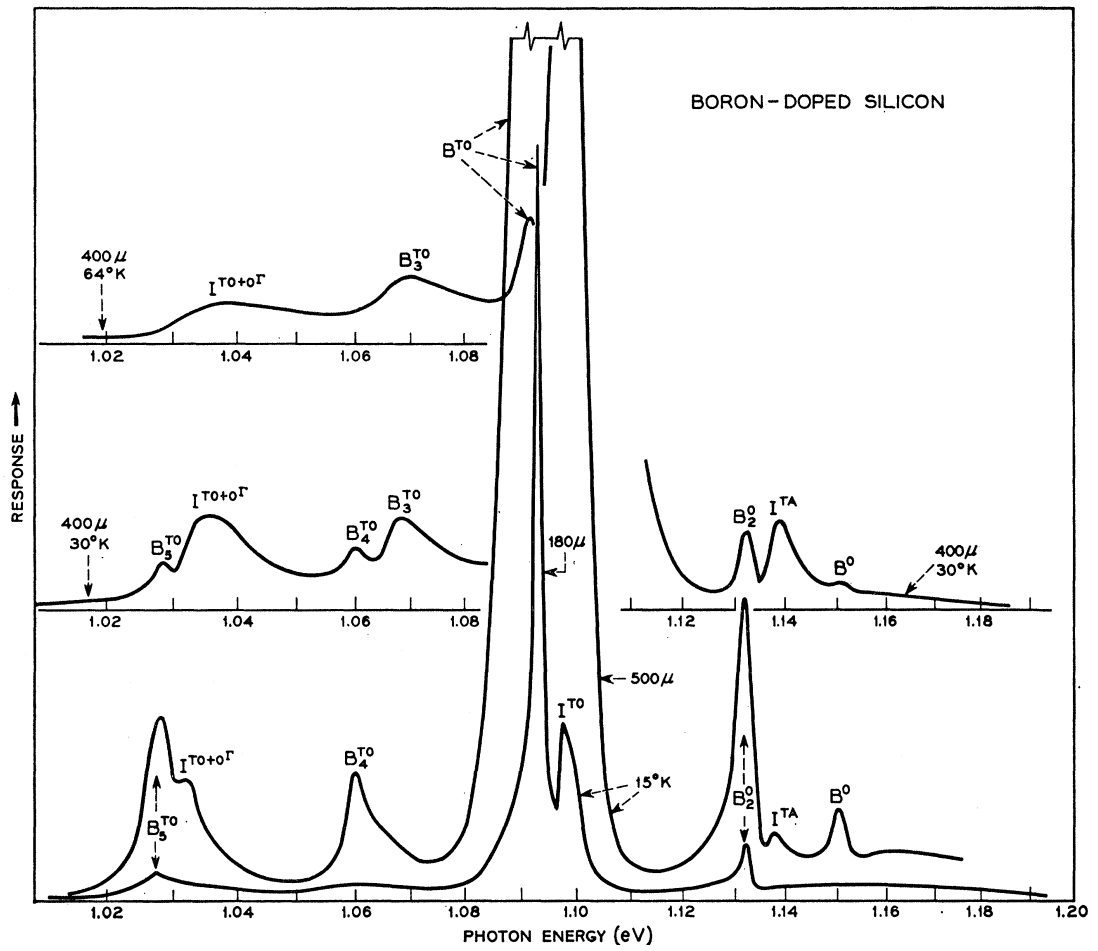


Figure 27: Boron doped ($6 \cdot 10^{16} cm^{-3}$) Si PL specter from [12]

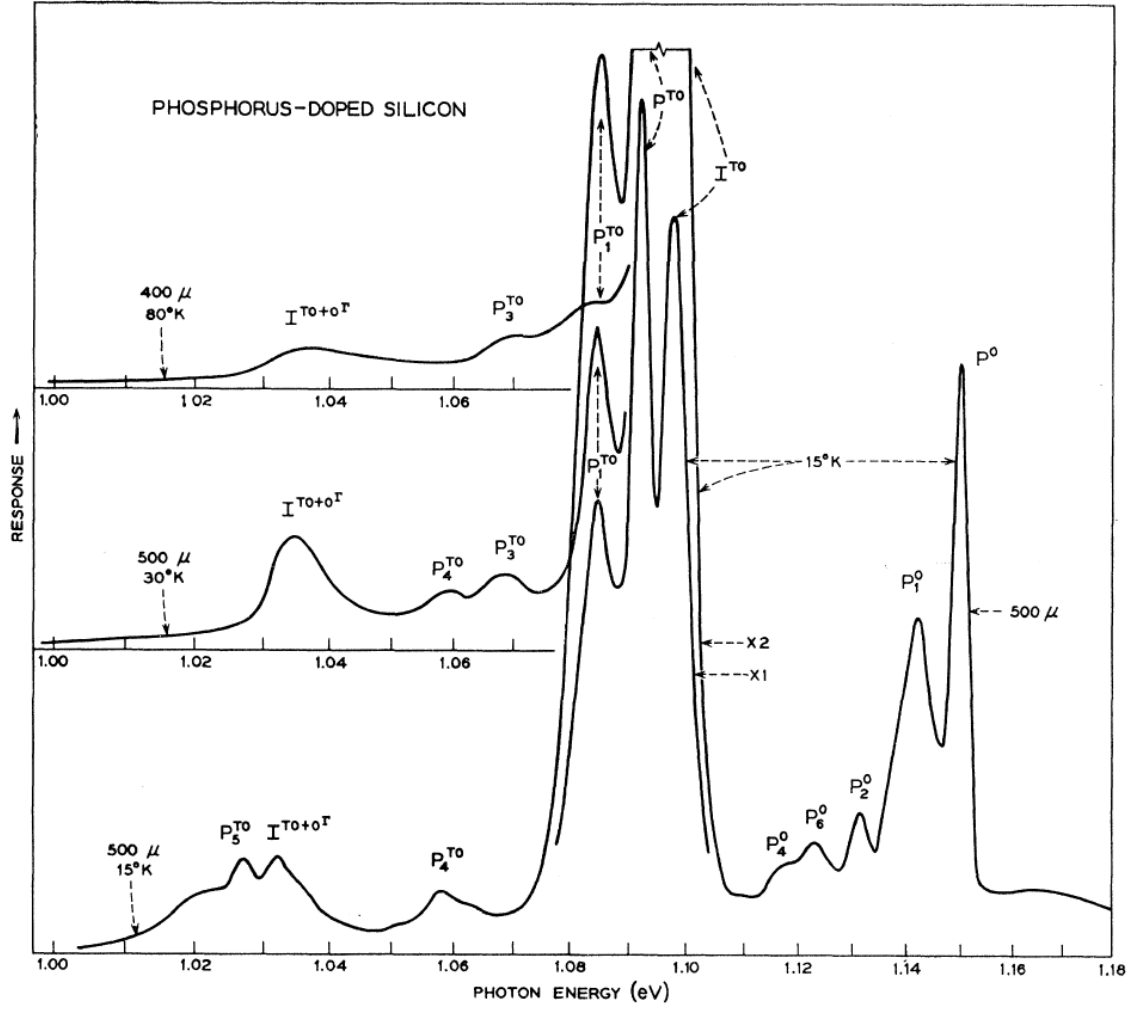


Figure 28: Phosphorus doped ($8 \cdot 10^{16} \text{cm}^{-3}$) Si PL specter from [12]

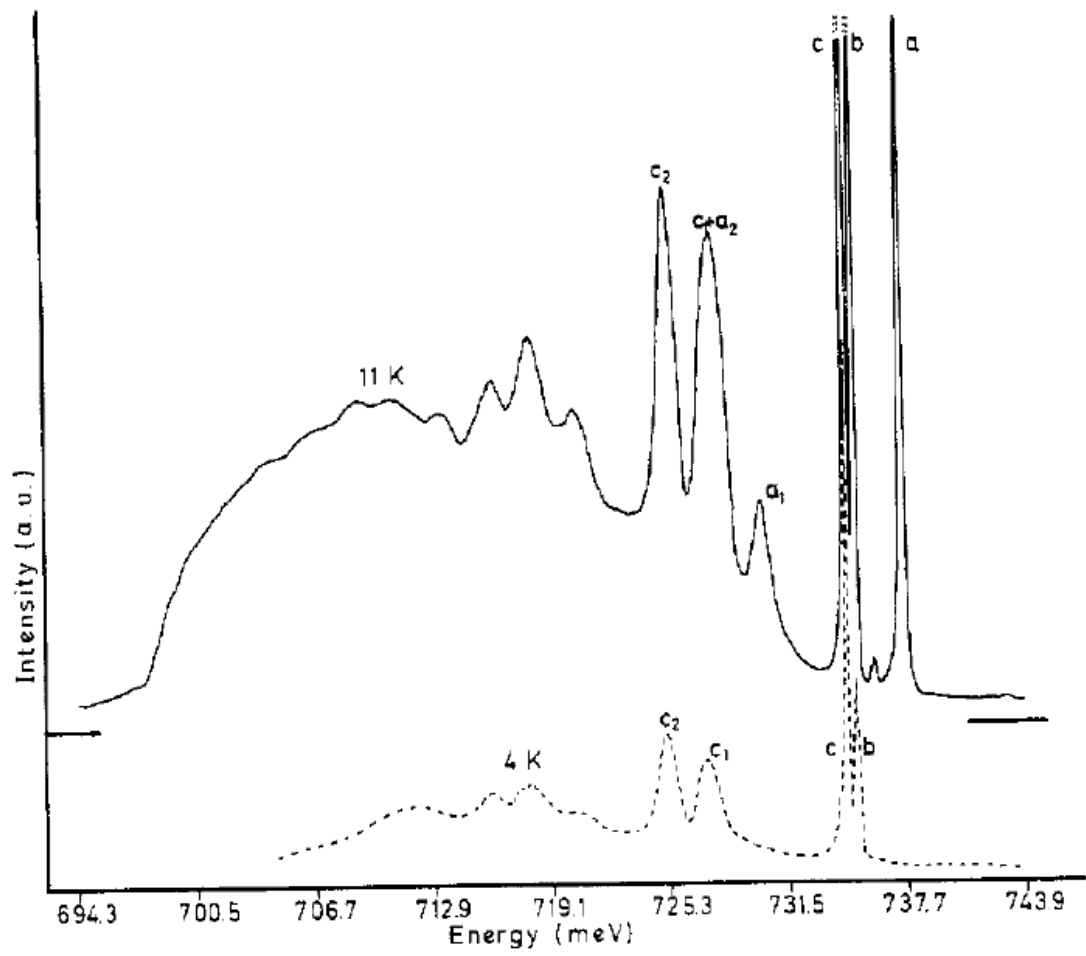


Figure 29: Iron diffused Si sample at two different temperatures from [22]

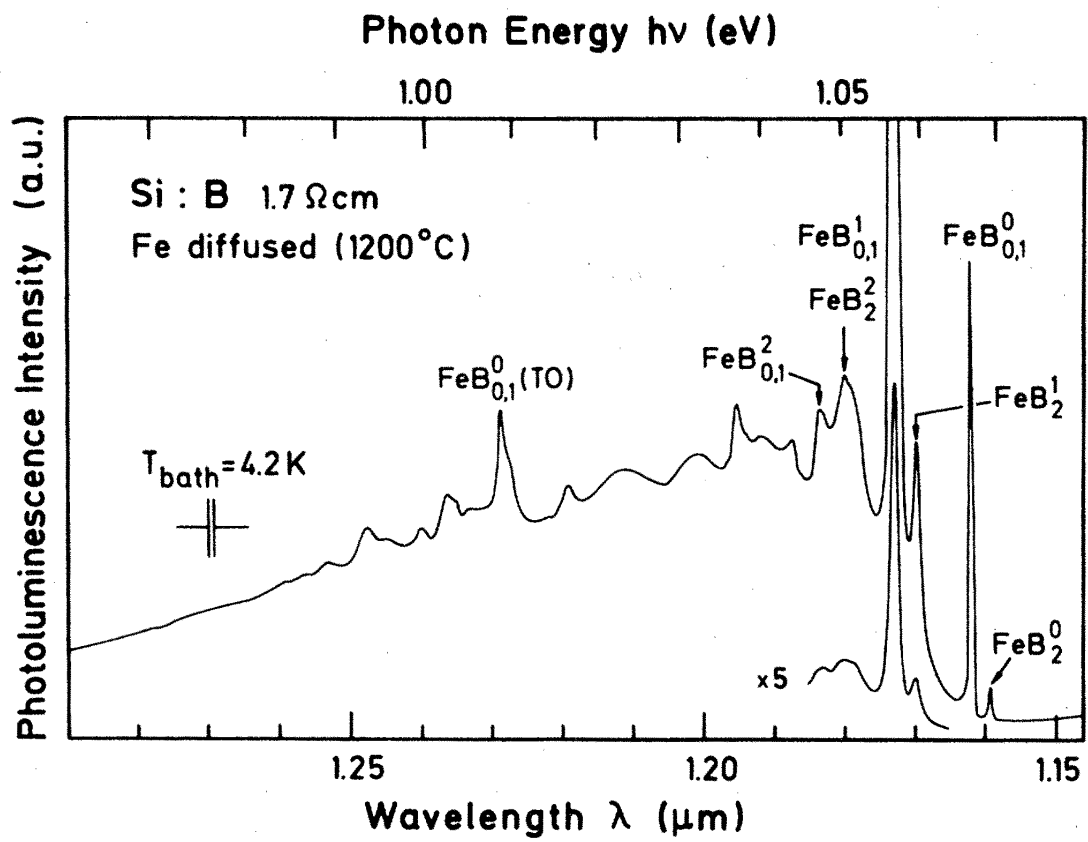


Figure 30: Iron diffused boron doped Si sample from [23]

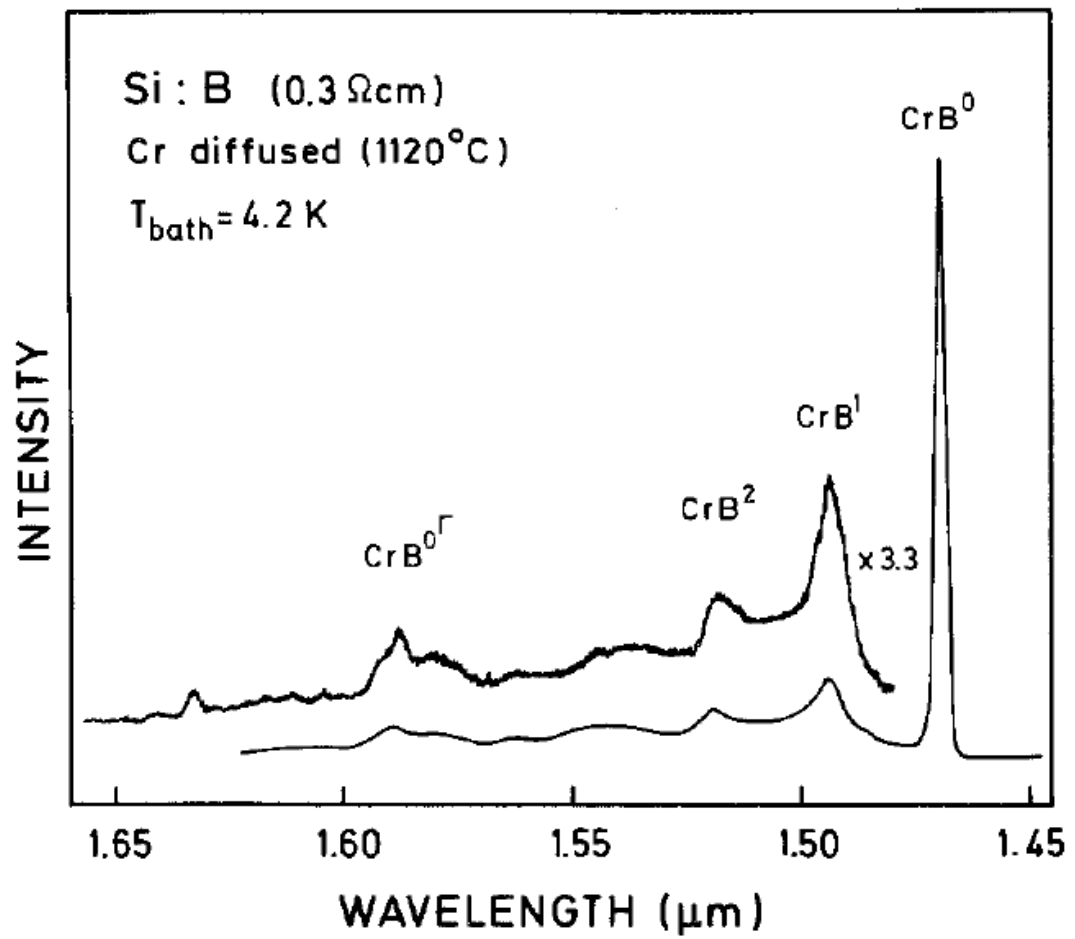


Figure 31: Chromium diffused Boron doped Si sample from [18]

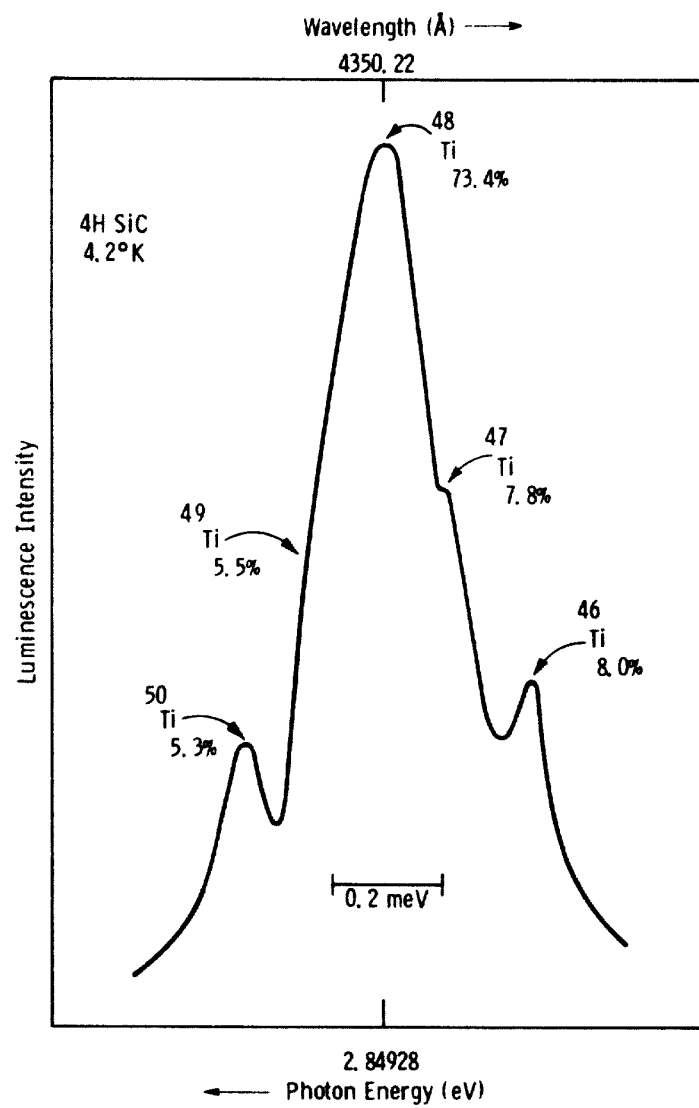


Figure 32: Titanium PL from Ti contaminated 4H SiC

Ref.	Sample type	Excitation process	Area	Processing	Doping
[14]	mc-Si	532nm Nd:YVO ₄	0.1mW/10 μ m diameter	Sawing damage etched by HNO ₃ /HF	B-doped
[33]	Cz-Si	Kr ion laser 647nm	10 μ m		Undoped
[1]	Cz-Si	Xenon lamp	50mW on 3mm modulated at 9Hz	deformed by bending at 850° C	undoped, weak n and p
[10]	mc-Si	800nm AlGaAs laser	Pulsed 300mW / 3mm		Block-casting technique for Baysix
[13]	mc-Si	800nm AlGaAs at 140mW		Produced by EFG	
[51]	mc-Si and FZ-Si	Ar ion 514nm at 300mW	100 μ m	Produced by EFG	boron doped $10^{15}cm^{-1}$
[3]	FZ-Si	Kr-ion 647nm, Ar-ion 415nm and Nd-YAG 1064nm		Deformed a 650° C and 850° C	residual $10^{12}cm^{-3}$ boron
[34]	mc-Si	Nd:YVO 532nm	6mW, 10 μ m diameter	Slicing damage etched off by HNO ₃ /HF	boron doped
[18]	FZ-Si and CZ-Si		50mW laser	Etched with HNO ₃ /HF. Chromium diffused	boron doped
[23]	FZ-Si	Ar+ 514nm	500mW	Fe diffused	boron doped
[22]	FZ-Si	Argon laser		Fe diffusion	undoped
[21]		Ar ⁺ 514nm at 1.5W			Cu doped
[9]	FZ-Si	Ar ⁺ 514nm		Heated above a Bunsen burner	Doped with Cu and/or Fe
[52]	mc-Si		6W/cm ²	Polished by HNO ₃ /HF	Undoped
[12]	CZ-Si	200W mercury arc 2.5eV			Undoped and doped
[30]		Ar ⁺ or Kr ⁺ laser 0.6W	0.8mm diameter	Dislocations by bending at 700° C	phosphorus doped

Table 6: Sample types and procedures

C Abbreviations

Abbreviation	Description
B_{TO}	TO phonon replica of the Boron bound exciton
BE	Bound exciton
D_a	Broad background emission
D_b	Oxygen impurity band
CZ-Si	Czochralski processed Silicon
D1	Dislocation related line 1
D1'	Dislocation related line 1 for mc-Si
D2	Dislocation related line 2
D2'	Dislocation related line 2 for mc-Si
D3	Dislocation related line 3
D3'	Dislocation related line 3 for mc-Si
D4	Dislocation related line 4
D4'	Dislocation related line 4 for mc-Si
EBIC	Electron beam induced current
EBSP	Electron Backscatter Diffraction Pattern
EHD	Electron Hole Droplet
FE	Free exciton
FZ-Si	Float-zone silicon
EFG	Edge-define Film-fed Growth
mc-Si	Multicrystalline silicon
R1BB	One phonon replica of band edge emission
R2BB	Two phonon replica of band edge emission
SA GB	Small Angle Grain Boundary
ZPL	Zero Phonon Line

Table 7: Abbreviations

D Matlab code

D.1 Main plot code

```
% Author: Jon Skarpeteig

clear, clc, close all % clear all variables, window, and close all windows
%set( 0, 'DefaultFigurePaperType', 'A5' );
%set( 0, 'DefaultFigurePaperUnits', 'centimeters' );

fontsize = 14;
delimiter = '\t';

%% MH2-Q3-210

% Line mapping
Mapping_noise = '..\Results\april-28-2010\MH2-Q3-210-B2\dislocationsmappingtake2withnoise';
Mapping_noise = get_result_from_dir(Mapping_noise, delimiter, 1);

for i=1:10
    Result = get_result_from_dir(strcat('..\Results\april-28-2010\MH2-Q3-210-B2\dislocationsmappingtake2withnoise', num2str(i), '.tif'));
    Result = dark_current_noise_removal(Result, Mapping_noise);
    Result = dark_current_noise_removal(Result, 0);
    plot_result(Result, 1, 'ev', '20s integrating time', 'MH2-Q3-210 Line mapping', fontsize);
end
print -depsc 'Processed_results\MH2-mapping-small_steps-20s';

for i=1:20
    Result = get_result_from_dir(strcat('..\Results\april-28-2010\MH2-Q3-210-B2\dislocationsmappingtake2withnoise', num2str(i), '.tif'));
    Result = dark_current_noise_removal(Result, Mapping_noise);
    Result = dark_current_noise_removal(Result, 0);
    plot_result(Result, 2, 'ev', '20s integrating time', 'MH2-Q3-210 Line mapping', fontsize);
end
print -depsc 'Processed_results\MH2-mapping-5_small_steps-20s';

% Low temperature
MH2_noise_20s = '..\Results\april-28-2010\MH2-Q3-210-B2\Noise-20s-during-spot3';
MH2_noise_20s = get_result_from_dir(MH2_noise_20s, delimiter, 1);

% Area 1
MH2_area1 = '..\Results\april-28-2010\MH2-Q3-210-B2\spot1-goodspot';
MH2_area1 = get_result_from_dir(MH2_area1, delimiter, 1);
MH2_area1 = dark_current_noise_removal(MH2_area1, MH2_noise_20s);
plot_result(MH2_area1, 2, 'ev', '20s integrating time', 'MH2-Q3-210 B2 Area 1', fontsize);
print -depsc 'Processed_results\MH2-Area1-dislocation_free-20s';
```

```

% Area 2
MH2_area2 = '..\Results\april-28-2010\MH2-Q3-210-B2\spot2-dislocationline\';
MH2_area2 = get_result_from_dir(MH2_area2,delimiter,1);
MH2_area2 = dark_current_noise_removal(MH2_area2,MH2_noise_20s);
plot_result(MH2_area2,3,'ev','20s integrating time','MH2-Q3-210 B2 Area 2',fontsize,14);
print -depsc 'Processed_results\MH2-Area2-dislocation_line-20s';
% Area 3
MH2_area3 = '..\Results\april-28-2010\MH2-Q3-210-B2\spot3-dislocation2\Signal-20s\';
MH2_area3 = get_result_from_dir(MH2_area3,delimiter,1);
MH2_area3 = dark_current_noise_removal(MH2_area3,MH2_noise_20s);
plot_result(MH2_area3,4,'ev','20s integrating time','MH2-Q3-210 B2 Area 3',fontsize,14);
print -depsc 'Processed_results\MH2-Area3-dislocation_dot-20s';

A = dead_pixel_correction(dlmread('..\Results\april-28-2010\Esi-q3-201-C\dislocationline\'));
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\Esi-q3-201-C\dislocationline\')));
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\Esi-q3-201-C\dislocationline\')));
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\Esi-q3-201-C\dislocationline\')));
Area3_noise_60s = A;

MH2_area3_60s = '..\Results\april-28-2010\MH2-Q3-210-B2\spot3-dislocation2\Signal-60s\';
MH2_area3_60s = get_result_from_dir(MH2_area3_60s,delimiter,1);
MH2_area3_60s = dark_current_noise_removal(MH2_area3_60s,Area3_noise_60s);
MH2_area3_60s = dark_current_noise_removal(MH2_area3_60s,0);
plot_result(MH2_area3_60s,4,'ev','60s integrating time','MH2-Q3-210 B2 Area 3',fontsize,14);
legend('20s integrating time','60s integrating time');
print -depsc 'Processed_results\MH2-Area3-dislocation_dot-60s';

% Room temperature
MH2_room_gd = '..\Results\mar-18-2010-roomtemperature\MH2-Q3-210-D\OK-40nmuselessd\';
MH2_room_gd = get_result_from_dir(MH2_room_gd,delimiter,1);
MH2_room_gd = dark_current_noise_removal(MH2_room_gd,0);
plot_result(MH2_room_gd,5,'ev','10s integrating time','MH2-Q3-210 D Room temperature',fontsize,14);

MH2_room_bad = '..\Results\mar-18-2010-roomtemperature\MH2-Q3-210-D\OK-40nmuselessd\';
MH2_room_bad = get_result_from_dir(MH2_room_bad,delimiter,1);
MH2_room_bad = dark_current_noise_removal(MH2_room_bad,0);
plot_result(MH2_room_bad,5,'ev','10s integrating time','MH2-Q3-210 D Room temperature',fontsize,14);
print -depsc 'Processed_results\MH2-room_temperature';

% At 70K
MH2_70K_bad = '..\Results\april-28-2010\MH2-Q3-210-B2\70K\dislocation\';
MH2_70K_bad = get_result_from_dir(MH2_70K_bad,delimiter,1);
MH2_70K_bad = dark_current_noise_removal(MH2_70K_bad,0);
plot_result(MH2_70K_bad,6,'ev','20s integrating time','MH2-Q3-210 B2 70K',fontsize,14);

MH2_70K_gd = '..\Results\april-28-2010\MH2-Q3-210-B2\70K\cleanarea\';
MH2_70K_gd = get_result_from_dir(MH2_70K_gd,delimiter,1);
MH2_70K_gd = dark_current_noise_removal(MH2_70K_gd,0);

```

```

plot_result(MH2_70K_gd,6,'ev','20s integrating time','MH2-Q3-210 B2 70K',fontsize,
print -depsec 'Processed_results\MH2-70K';

%}

%% ES1-Q3-201 C

% Room temperature
ES_room_gd = '..\Results\mar-18-2010-roomtemperature\Esi-q3-201-A\40nmoffdislocatio
ES_room_gd = get_result_from_dir(ES_room_gd,delimiter,1);
ES_room_gd = dark_current_noise_removal(ES_room_gd,0);
plot_result(ES_room_gd,7,'ev','10s integrating time','ES1-Q3-201 A Room temperature

ES_room_bad = '..\Results\mar-18-2010-roomtemperature\Esi-q3-201-A\40nmoffdislocatio
ES_room_bad = get_result_from_dir(ES_room_bad,delimiter,1);
ES_room_bad = dark_current_noise_removal(ES_room_bad,0);
plot_result(ES_room_bad,7,'ev','10s integrating time','ES1-Q3-201 A Dislocation fre
print -depsec 'Processed_results\ES1-room_temperature';

% Low temperature
ES_noise_10s = '..\Results\april-28-2010\Esi-q3-201-C\dislocationline-Area4>Noise-
ES_noise_10s = get_result_from_dir(ES_noise_10s,delimiter,1);

% Area 1
ES_Area1 = '..\Results\april-28-2010\Esi-q3-201-C\Good-area1\';
ES_Area1 = get_result_from_dir(ES_Area1,delimiter,1);
ES_Area1 = dark_current_noise_removal(ES_Area1,ES_noise_10s);
plot_result(ES_Area1,8,'ev','10s integrating time','ES1-Q3-201 C Area 1',fontsize,
print -depsec 'Processed_results\ES1-Area1_dislocation_free-10s';

% Area 2
ES_Area2 = '..\Results\april-28-2010\Esi-q3-201-C\dislocationspotArea2\';
ES_Area2 = get_result_from_dir(ES_Area2,delimiter,1);
ES_Area2 = dark_current_noise_removal(ES_Area2,ES_noise_10s);
plot_result(ES_Area2,9,'ev','10s integrating time','ES1-Q3-201 C Area 2',fontsize,
print -depsec 'Processed_results\ES1-Area2_dislocation_spot-10s';

% Area 3
ES_Area3 = '..\Results\april-28-2010\Esi-q3-201-C\grain_boundary-Area3\Signal-10s\
ES_Area3 = get_result_from_dir(ES_Area3,delimiter,1);
ES_Area3 = dark_current_noise_removal(ES_Area3,ES_noise_10s);
plot_result(ES_Area3,10,'ev','10s integrating time','ES1-Q3-201 C Area 3',fontsize,
print -depsec 'Processed_results\ES1-Area3_grain_boundary-10s';

A = dead_pixel_correction(dlmread('..\Results\april-28-2010\Esi-q3-201-C\dislocatio
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\apri
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\apri
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\apri

```



```

Area3_noise_60s = A;
ES_Area3 = '..\Results\april-28-2010\Esi-q3-201-C\grain_boundary-Area3\Signal-60s';
ES_Area3 = get_result_from_dir(ES_Area3,delimiter,1);
ES_Area3 = dark_current_noise_removal(ES_Area3,Area3_noise_60s);
plot_result(ES_Area3,10,'ev','10s integrating time','ES1-Q3-201 C Area 3',fontsize,12);
legend('10s integrating time','60s integrating time');
print -depsc 'Processed_results\ES1-Area3_grain_boundary_60s';

% Area 4
ES_signal_10s = '..\Results\april-28-2010\Esi-q3-201-C\dislocationline-Area4\Signal-10s';
ES_signal_10s = get_result_from_dir(ES_signal_10s,delimiter,1);
ES_10s = dark_current_noise_removal(ES_signal_10s,ES_noise_10s);
plot_result(ES_10s,11,'ev','10s integrating time','ES1-Q3-201 C Area 4',fontsize,12);
print -depsc 'Processed_results\ES1-Area4_dislocation_line-10s';

ES_noise_60s = '..\Results\april-28-2010\Esi-q3-201-C\dislocationline-Area4\Noise-60s';
ES_noise_60s = get_result_from_dir(ES_noise_60s,delimiter,1);
ES_signal_60s = '..\Results\april-28-2010\Esi-q3-201-C\dislocationline-Area4\Signal-60s';
ES_signal_60s = get_result_from_dir(ES_signal_60s,delimiter,1);
ES_60s = dark_current_noise_removal(ES_signal_60s,ES_noise_60s);
plot_result(ES_60s,11,'ev','60s integrating time','ES1-Q3-201 C Area 4',fontsize,12);
legend('10s integrating time','60s integrating time');
print -depsc 'Processed_results\ES1-Area4_dislocation_line-60s';
%}

%% R6-Q3-210 A

% Low temperature

Noise = '..\Results\april-28-2010\R6-Q3-201-A\NOISE\';
Noise = get_result_from_dir(Noise,delimiter,1);
Area1_dislocation_line = '..\Results\april-28-2010\R6-Q3-201-A\Dislocation-area1\';
Area2_dislocation_dot = '..\Results\april-28-2010\R6-Q3-201-A\Area2\';
Area3_clean_area = '..\Results\april-28-2010\R6-Q3-201-A\Area3_clean\';

Area1 = get_result_from_dir(Area1_dislocation_line,delimiter,1);

A = dead_pixel_correction(dlmread('..\Results\april-28-2010\R6-Q3-201-A\NOISE\20s-r');
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\R6-Q3-201-A\NOISE\20s-r');
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\R6-Q3-201-A\NOISE\20s-r');
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\R6-Q3-201-A\NOISE\20s-r');
A = matrix_align_and_glue_reverse(A,dead_pixel_correction(dlmread('..\Results\april-28-2010\R6-Q3-201-A\NOISE\20s-r');
Area1_noise = A;

Area1 = dark_current_noise_removal(Area1,Area1_noise);
plot_result(Area1,12,'ev','20s integrating time','R6-Q3-210 A Area 1',fontsize,'b',12);
print -depsc 'Processed_results\R6-Area1_dislocation_line-20s';

```

```

Area2 = get_result_from_dir(Area2_dislocation_dot,delimiter,1);
Area2 = dark_current_noise_removal(Area2,Noise);
plot_result(Area2,13,'ev','20s integrating time','R6-Q3-210 A Area 2',fontsize,'b',
print -depsc 'Processed_results\R6-Area2_dislocation_dot-20s';

Area3 = get_result_from_dir(Area3_clean_area,delimiter,1);
Area3 = dark_current_noise_removal(Area3,Noise);
plot_result(Area3,14,'ev','20s integrating time','R6-Q3-210 A Area 3',fontsize,'b',
print -depsc 'Processed_results\R6-Area3_clean_area-20s';
%}

%% Dark current removal plots

% Dark current with shutter closed
Result_dark_noise = dlmread('..\Results\april-28-2010\Noise\20s-shutter-closed-300gr
Result_dark_noise = dead_pixel_correction(Result_dark_noise);
plot_result(Result_dark_noise,15,'nm','20s integrating time','Dark current removal

% Background noise
Result_bg_noise = dlmread('..\Results\april-28-2010\Noise\20s-background-noise\20s
Result_bg_noise = dead_pixel_correction(Result_bg_noise);
plot_result(Result_bg_noise,15,'nm','x','x',fontsize,'r',0);

% Offset estimation
A = Result_dark_noise;
Ay = A(:,2); % Amplitude values
Ay = sgolayfilt(Ay,1,25); % 1st order filtering
C = [A(:,1),Ay];
plot_result(C,15,'nm','x','x',fontsize,'c',0);

print -depsc 'Processed_results\Dark_current_and_background_noise-20s';

% Dark current noise removal
Result = dark_current_noise_removal(Result_bg_noise,Result_dark_noise);
plot_result(Result,16,'nm','20s integration time','Dark current offset removed',for
plot_result(Result,16,'nm','20s integration time','Dark current offset removed',for

print -depsc 'Processed_results\Dark_current_removed-20s';
%}

%% Dead pixel proof plots

% Dead pixels clearly visible
Result_dark_40s = dlmread('..\Results\april-28-2010\Noise\40s-shutter-closed-300gr
plot_result(Result_dark_40s,17,'nm','40s integrating time','Dark current',fontsize,
% Write to .eps for use in latex

```

```

print -depsec 'Processed_results\Dark_current-40s';

% Dead pixels corrected
Result_dark_40s = dead_pixel_correction(Result_dark_40s);
plot_result(Result_dark_40s,17,'nm','40s integrating time','Dark current',fontsize,12);
print -depsec 'Processed_results\Dark_current-40s_corrected';

% Dead pixels less clearly visible
Result_dark_10s = dlmread('..\Results\april-28-2010\Noise\10s-shutter-closed-300gr');
plot_result(Result_dark_10s,18,'nm','10s integrating time','Dark current',fontsize,12);
print -depsec 'Processed_results\Dark_current-10s';

% Dead pixels corrected
Result_dark_10s = dead_pixel_correction(Result_dark_10s);
plot_result(Result_dark_10s,18,'nm','10s integrating time','Dark current',fontsize,12);
print -depsec 'Processed_results\Dark_current-10s_corrected';
%}

```

D.2 Dead pixel correction

```

function [C] = dead_pixel_correction(A)
% Copy neighbour value on defect pixels in InGaAs camera.
C = A;
C(401,2) = A(400,2); % Defective (slightly to low)
C(723,2) = A(722,2); % Defective (slightly to high)
C(933,2) = A(932,2); % This pixel is dead (too high values)
C(873,2) = A(872,2); % This pixel is dead (too low values)
end

```

D.3 Dark current noise estimation removal

```

function [C] = dark_current_noise_removal(A,B)
% Smoothens noise, and find min value, and remove offset.
% Negative values from noise are truncated to 0.
% A and B MUST be of equal length!

if (length(A) ~= length(B))
    X = 'Length different from B';
    B = [];
end
if (isempty(B))
    % No noise is measured, remove a static offset instead.

```

```

C = A;
Ay = A(:,2); % Amplitude values
Ay = sgolayfilt(Ay,1,255); % 1st order filtering
offset = min(Ay); % Minimum offset, from noise averaging

for i=1:length(A),
    new_value = A(i,2)-offset;
    if (new_value < 0)
        new_value = 0;
    end
    C(i,2) = new_value;
end
else
    % B matrix is the noise measurement
    % - filter, and remove offset
    C = A;
    By = B(:,2); % Amplitude values
    OFFSET = sgolayfilt(By,1,25); % 1st order filtering

    for i=1:length(A),
        new_y_value = (C(i,2) - OFFSET(i));
        % white noise artifacts can result in < 0 values which are
        % clearly not possible in real life
        if (new_y_value < 0)
            new_y_value = 0;
        end
        C(i,2) = new_y_value;
    end
end
end
end

```

D.4 Read result files from directory

```

function [C] = get_result_from_dir(dname,delimiter,drop_rightsides)
% Reads all files in a directory, and return matrix elements
% separated by delimiter from file contents

C = 0;

% Read directory
files = dir(dname);

% Sort filenames in dir
filenames = {files.name};

% Sort numbers in string logically

```

```

[dummy, index] = sort_nat(filenamees);

% re-index the files array:
files = files(index);

% Combine files to one large array
for i=1:length(files),
    if (files(i).name == '.') % Do nothing
    elseif (strcmp(files(i).name, '..')) % Do nothing
    elseif (strcmp(files(i).name, '.svn')) % Do nothing
    else
        % Read file contents into memory
        A = dlmread([dname, files(i).name], delimiter);

        % Filter out dead pixels in the InGaAs camera
        A = dead_pixel_correction(A);
        if (0 == C)
            C=A;
        else
            if (drop_rightside == 0)
                C = matrix_align_and_glue(C,A);
            else
                C = matrix_align_and_glue_reverse(C,A);
            end
        end
    end
end
end
end
end

```

D.5 Remove overlap and glue intervals

```

function [C] = matrix_align_and_glue_reverse(A,B)

overlapIndex = 0;

% Drop the left side in the interval
for i=1:length(B),
    if (A(length(A),1) < B(i,1))
        overlapIndex = i;
        break;
    end
end

% Define new array length
sizeA = length(A);
sizeB = length(B);

```

```

new_array_size = (sizeA+sizeB-overlapIndex);

% Define right length of array
temp_C = zeros([new_array_size 2]);

% Add existing elements
for j = 1:length(A),
    temp_C(j,1) = A(j,1);
    temp_C(j,2) = A(j,2);
end

% Add new elements
for k = 1:(length(B)-overlapIndex),
    temp_C((length(A)+k),1) = B(overlapIndex+k,1);
    temp_C((length(A)+k),2) = B(overlapIndex+k,2);
end

C = temp_C;
end

```

D.6 Filter and plot results

```

function plot_result(Result,fig_number,type,legend1,title1,fontsize,plot_type,sgofilter_strength)

% Define X and Y values
Ax = Result(:,1);
Ay = Result(:,2);

% Filter
if (sgofilter_strength > 0)
    % 1st order filtering
    Ay = sgolayfilt(Ay,1,sgofilter_strength);
end

% Calculate eV values if needed
if (strcmp(type,'ev'))
    Ax = nm_to_ev(Ax);
    xlabel1 = 'Energy [eV]';
else
    xlabel1 = 'Wavelength [nm]';
end

% Detect same figure plot
cf = get(0,'CurrentFigure');
fill_info = 0;
if (isempty(cf))

```

```

        fill_info = 1;
    end
    if (cf ≠ fig_number)
        fill_info = 1;
    end

    % Plot
    fig = figure(fig_number);

    if (fill_info)
        axes1 = axes('Parent',fig,'FontSize',fontsize);
        box(axes1,'on');

        hold(axes1,'all');
        hold on;
    end

    plot(Ax,Ay,plot_type);

    % If no figure exists, input info
    if (fill_info) % Don't add info twice
        legend(legend1);
        title(title1);
        ylabel('Counts');
        xlabel(xlabel1);
    end
end
end

```